

EXHIBIT 4



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Expert Report of Nicholas Xuanlai Fang, Ph.D.

Dated: Dec 16, 2019

Styller, et al. v. Hewlett-Packard Fin. Servs. Co., et al.

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I. Qualifications

My name is Xuanlai Fang (alias Nicholas). I am a professor of Mechanical Engineering at MIT. I specialize in optics, photonics and micro/nano manufacturing.

I obtained B.S and M.S. degree in Physics from Nanjing University, China, and a Ph.D. in Mechanical Engineering from University of California, Los Angeles. I specialized in nanophotonics and nanofabrication.

From 2004 to 2010, I served as Assistant Professor at the University of Illinois where I taught classes in manufacturing processes, nanomanufacturing, engineering materials and introduction to nanoscience and technology.

From 2011 to present, I served as Associate Professor and then Full Professor (with Tenure) at Massachusetts Institute of Technology. At MIT I taught classes in instrumentation and measurement, optics and photonic materials. I also regularly published academic research in leading journals on nanophotonics and nanomanufacturing. I am an active member of the Optical Society of America (OSA), the Institute of Electrical and Electronics Engineering (IEEE), the American Society of Mechanical Engineers (ASME), and the Materials Research Society. A copy of my CV is attached as Exhibit 1 to this report. A complete list of my publications over past ten years is attached as Exhibit 2 of this report.

I have substantial experience using optical imaging and interferometry instruments for measuring diffractive optical structures and devices for national laboratories and industry collaborators. I have conducted research on a wide range of optical devices and systems such as near-field holographic system for characterization

of metallic nanostructures, and the design of thin metallic film light absorbers using hologram principles.

I have not previously testified as an expert at trial or by deposition.

II. Assignment

I have been instructed by Plaintiffs' counsel JOFFE LAW P.C. to inspect the H3C trademark holographic logos attached to the subject transceivers to determine whether the logos bear any indicators of counterfeiting described in H3C's security bulletin (Exhibit 3 to this Report) and in H3C's verification report (Exhibit 4 to this Report), and to produce an expert report based on the methodology and the results of my inspection.

I have been compensated for my services in this matter at the rate of \$425 per hour.

I reserve the right to supplement this expert report based on any additional work that I may be asked to do.

III. Documents and Materials Reviewed

As part of my assignment, I have reviewed the H3C security bulletin explaining the security features of its trademark logos on the transceivers manufactured after May 10, 2010 (in Mandarin, which is my first language).

I have also reviewed a report produced by Defendants stamped DEF0002807-DEF0002817, which I understand Defendants refer to as H3C's verification report of the transceivers seized from Plaintiffs by the Chinese police (also in Mandarin). The H3C security bulletin and the verification report are attached as Exhibits 3 and 4 to this report (with English translations provided by Plaintiffs).

I have also reviewed the complaint filed by Plaintiffs (Case 1:16-cv-10386-LTS, Document 101 filed 08/04/17) for background purposes. I have also reviewed the Court's protective order (Case 1:16-cv-10386-LTS, Document 188 filed 02/07/19) and executed an acknowledgment form attached as an exhibit.

I have also reviewed an excel spreadsheet listing the subject transceivers by their unique serial numbers, and recorded the results of my inspection on that spreadsheet attached as Exhibit 5 to this Report.

I have also reviewed pictures of two holographic H3C logos provided by Plaintiffs attached as Exhibit 6 to this Report.

I have inspected **779** transceivers delivered to me by Plaintiffs and examined **394** holographic H3C trademark logos for the occurrence of the indications of counterfeiting described in H3C's security bulletin and verification report, as explained below.

IV. Summary of Opinion

My overall opinion is that 343 of the inspected H3C hologram trademark logos affixed to the subject transceivers (87.1% of the 394 logos examined) show **one or more indicators of counterfeiting** described in the H3C security bulletin or in the H3C verification report. I explain the bases for my opinion in the sections below.

V. Testing methodology

I first reviewed the H3C securities bulletin and the verification report for the indicators of counterfeit H3C holographic logos.

A. The H3C security bulletin. The bulletin describes H3C security holographic labels for its products, including transceivers, used by H3C since May 2010. The bulletin demonstrates the specific optical patterns that should be visible if an

authentic holographic logo is viewed from different angles. The pattern includes four perimeter dots visible in different positions as bright or dark spots if viewed from four different angles, and a vertical bright center dot visible if viewed from the left or right angles (H3C bulletin, page 2 & Figure 2.1).



Figure 1. H3C security bulletin Figure 2.1 illustrating specific optical patterns that should be visible if an authentic holographic logo is viewed from different angles.

The security bulletin also mentions the old version of the logo (with background Chinese characters) that does not contain those security features (H3C bulletin, page 1 and the illustration of the old and new logos):



Figure 2. The H3C security bulletin illustration of the old version of the logo (with Chinese characters) (left panel) and the new version of the logo (right panel).

B. The verification report. The verification report demonstrates several indicators of counterfeiting applicable to the H3C holographic logos summarized below.

(1) Logos pasted in the inconsistent positions. The verification report states that the authentic hologram labels are placed at the same location of the devices of same model number in accordance with H3C technical specifications, and the authentic logos cannot be removed and repasted without damaging the logo. Therefore, the wrong position of the labels with respect to the transceiver housing (verification report Figure 6) is regarded as an indicator of counterfeiting. Page DEF0002810. The verification report states that the logo position on the seized transceivers is inconsistent, and logos are irregularly pasted in various positions:

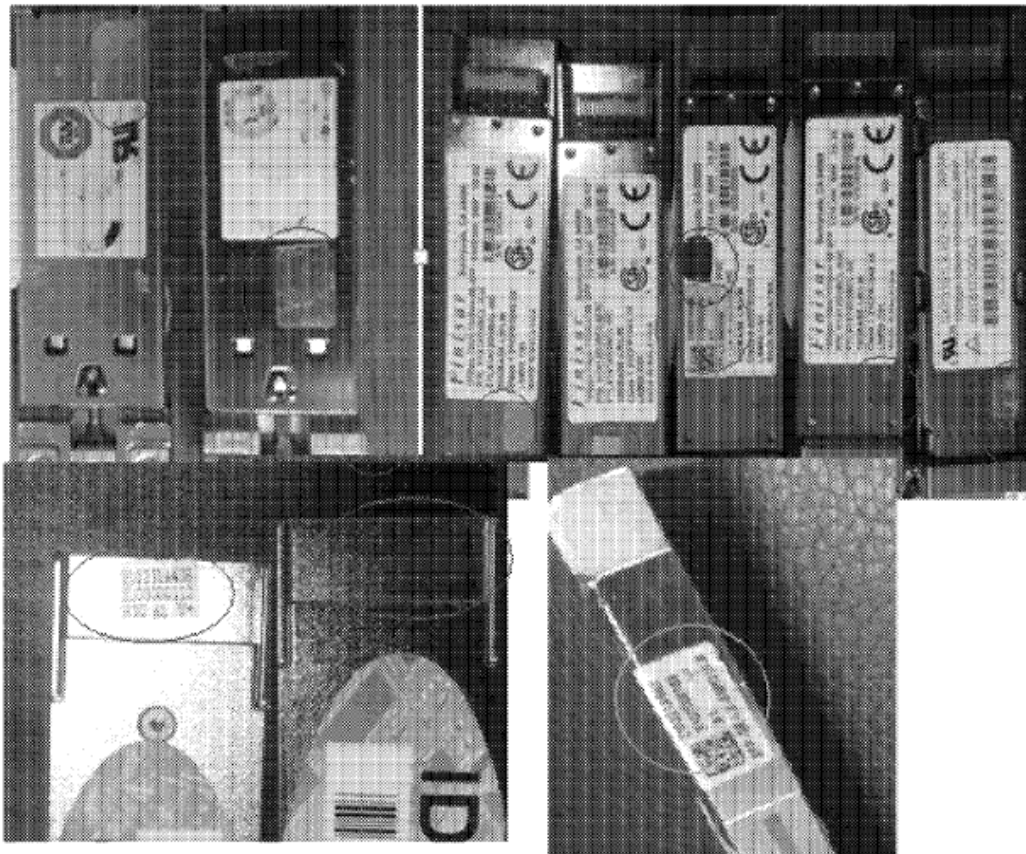


Figure 3. Verification report Figure 6 illustrating inconsistent pasting positions of the labels with respect to the transceiver housing.

(2) “H.3C” logos (with a dot appearing between “H” and “3C”) (verification report page DEF0002811 and Figure No. 8):



Figure 4. Verification report Figure 8 illustrating an “H.3C” logo (with a dot appearing between “H” and “3C”)

(3) Delamination of the top layer of the logos; (verification report pages DEF0002811-12 and Figure No. 9):

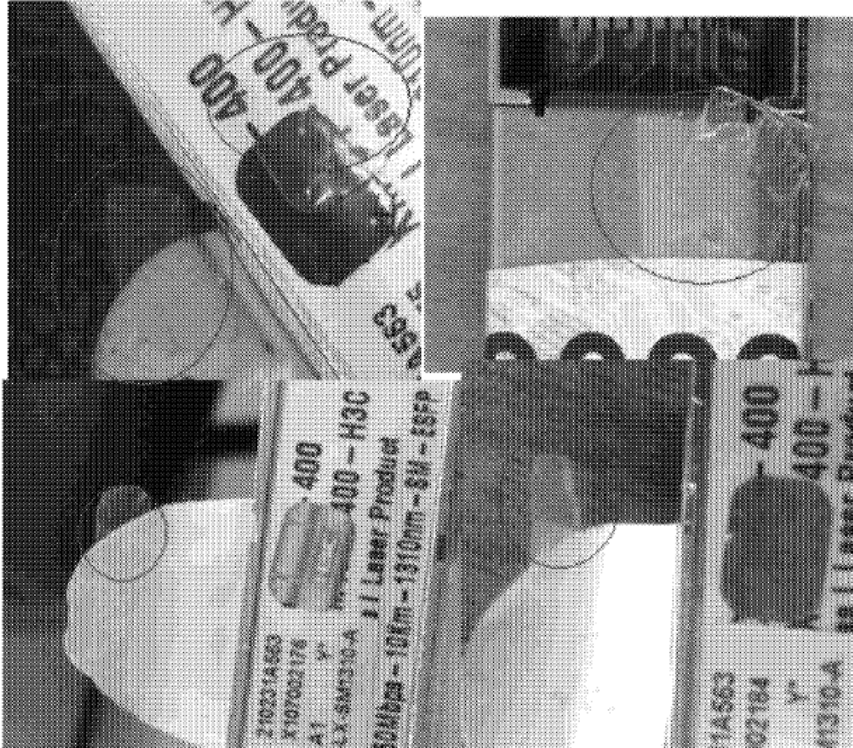


Figure 5. Verification report Figure 9 illustrating delamination of the top layer of the logos and examples of label fly-off.

(4) The off-centered position of the word “H3C” on the logos (verification report pages DEF0002812-13 and Figure No. 10):

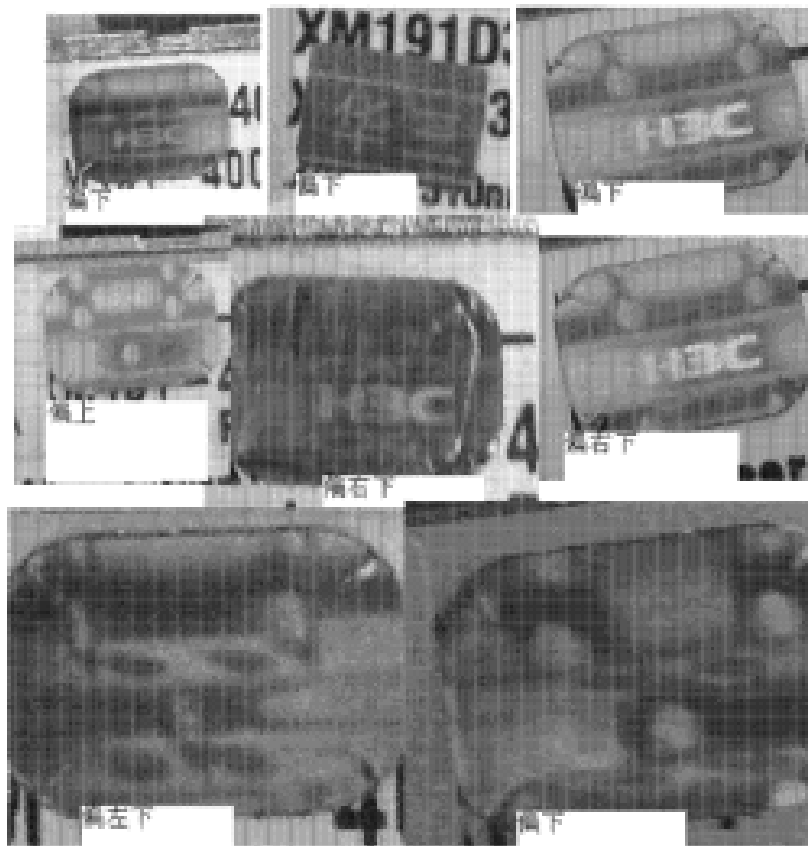


Figure 6. Verification report Figure 10 illustrating the off-centered position of the word “H3C” on the logos.

After reviewing the H3C security bulletin and the verification report for the indicators of counterfeiting, I then inspected the logos of the subject transceivers for the occurrence of these indicators of counterfeiting as follows.

Each transceiver being investigated was affixed to a wedge of fixed inclination angle (27.6° with respect to the horizontal plane) and illuminated by white light from normal incidence (from the digital microscope, 64mm above the logo) and from about 30° with respect to the horizontal plane. The fixed inclination angle of the sample and illumination of light irradiation allows consistent angle of view along the horizontal plan for recording of the reflected hologram pattern. The image of hologram label was recorded using a Celestron digital microscope with 200x magnification by means of the

integrated digital camera in my laboratory at MIT, and the photos were transmitted to a desktop computer. The effect of inclination angle in the optical recording is taken into consideration and the dimensions and relative shift are deducted by using the known width (7mm) and height (5mm) of hologram labels. The position of the word “H3C” with respect to the edges of the 7mm by 5mm label was measured from the photos and the relative shifts with respect to the center were documented. Such measurement procedure is comparable to the methodology taken by the scientific community for measuring visual parameters of a hologram, e.g., Bulygin¹ and A.S. Litvinenko et al.²

¹ F. V. Bulygin, “Measurement of the visual parameters of holograms”, Measurement Techniques, Vol. 48, No. 6, (2005).

² A.S. Litvinenko, A.A. Shelekhov, “The device of measurement of parameters of holograms”, 6th International Conference on Laser and Fiber-Optical Networks Modeling (2004).

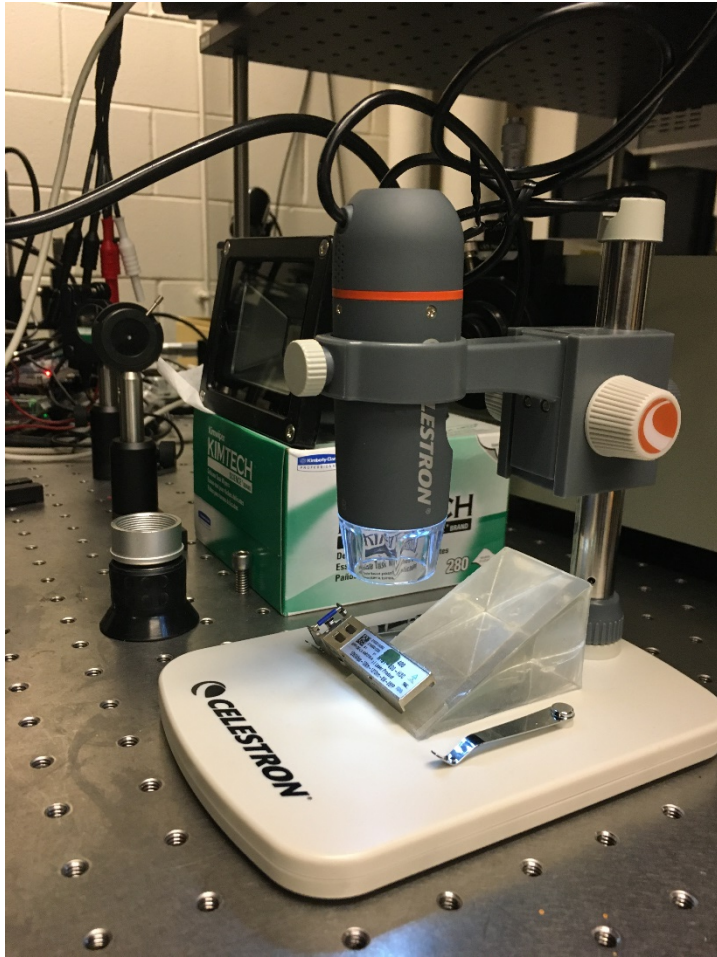


Figure 7. A photo of the digital microscope with an affixed transceiver.

VI. The Facts and Data Considered

Holographic security labels are reflective holograms that create an optical image. The visible effects of the hologram can be seen by tilting or rotating the image, or by moving its position or the light source. Modern computer-generated holograms are composed of small diffraction grating dots. Each dot is a grating whose period and orientation can be modified (under computer control). Grating dots are formed by two-beam interference on the photosensitive material (producing a sinusoidal profile grating

pattern).³ Viewers looking at this type of hologram from a certain position will see a mirror like reflection from those pixels which contain a grating whose fringe orientation directs reflected light towards their eye. Pixels which direct light elsewhere appear dark.

The perception of depth in the hologram labels is created by the relative displacement of elements associated with different planes with slight changes in the observation angle. This is tested by placing the hologram at 4 different orientations and record image of the holograms.

The hologram labels, 7mm wide and 5mm tall, of all small and large transceiver devices, were inspected for the occurrence of specific indicators of counterfeiting provided in the H3C bulletin and in the verification report (see Part V above).

According to literature on security labels,⁴ the specific, reproducible, and exact alignment of labels on the product is regarded an anti-counterfeiting tool. The H3C verification report states that “the bar code label and anti-counterfeit label attached to the H3C genuine transceiver body have strict technical specifications, and are regularly produced by trained workers on the assembly line. Therefore, the labeling position of the same type transceiver label is consistent.” Exhibit 4 (English translation).

VII. Summary of Findings

My findings with respect to the **779** subject transceivers are documented in the spreadsheet attached as Exhibit 5 to this Report. I summarize and explain those findings below:

³ Chih-Kung Lee, et al, “Optical configuration and color-representation range of a variable-pitch dot matrix holographic printer”, *Applied Optics*, Vol 39(1), pp. 40-53 (2000).

⁴ Mark Davison, Chapter 18, Security Labels, in *Pharmaceutical Anti-Counterfeiting: Combating the Real Danger from Fake Drugs*, published by John Wiley & Sons, Inc, 2011.

1. A total of **235** hologram labels on the transceiver devices received are found completely damaged. A photo illustrating completely damaged labels is provided as Figure 8 below.



Figure 8. Representative photos illustrating completely damaged hologram labels. The summary of damaged holograms can be found in table 1.

These hologram labels were not further investigated for indicators of counterfeiting (except as mentioned in point 3 below).

2. A total of **150** hologram labels on the transceiver devices received are found bearing Chinese logos on the hologram. A photo illustrating these logos is provided as Figure 9 below.



Figure 9. Representative photo illustrating Chinese character logos on hologram labels. The summary of the Chinese logo holograms can be found in table 1.

According to the H3C security bulletin, these holograms with Chinese characters were old logos manufactured prior to 2010. Because the H3C security bulletin and the verification report do not contain any criteria regarding the security features of the old trademark logos, these logos were not further investigated for indicators of counterfeiting (except as mentioned in point 3 below).

3. Although I did not further inspect the completely damaged and the old Chinese hologram logos, I observed inconsistent placing of those logos on the transceiver housing. The predominant position of the logo is on the lower right corner next to the CE Marking Certification label or the QR code label on the majority of the

inspected transceivers. However, a total of **25** inspected devices are found with the damaged or old hologram labels pasted on the lower left corner next of the CE Marking Certification label. The inconsistent pasting of the logo is regarded as an indicator of counterfeiting as noted on the verification report, Figure 6, page number DEF 0002810, reproduced as Figure 3 above.



Figure 10. Photos of representative samples with irregular and inconsistent pasting positions of the completely damaged logos.

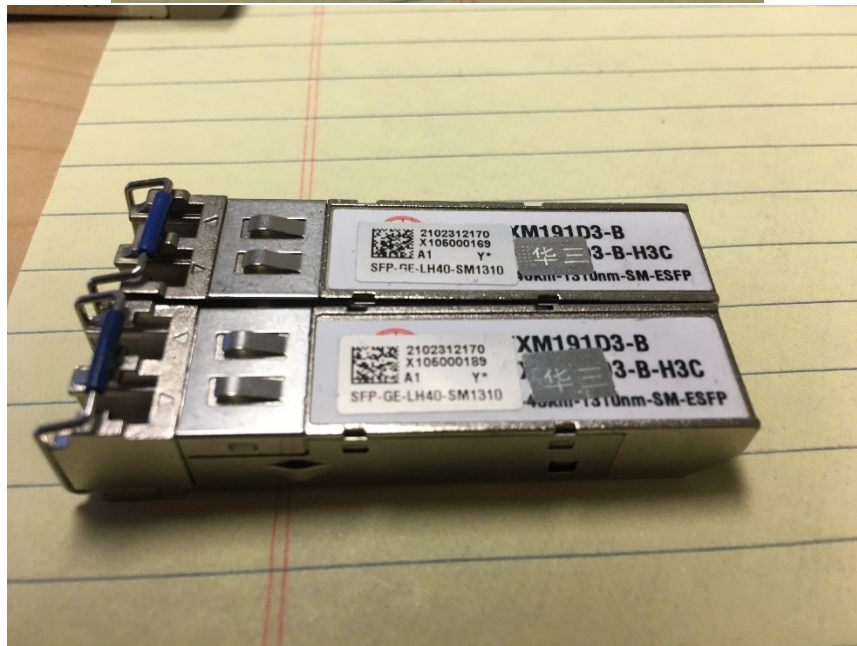
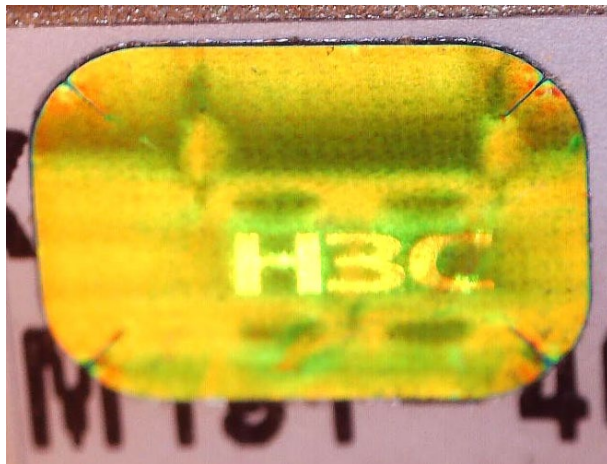


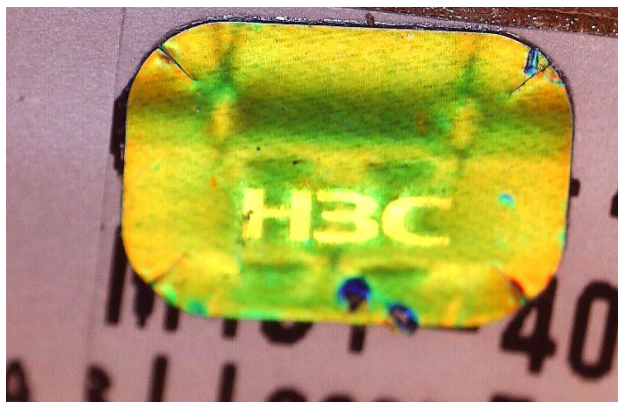
Figure 11 Photos of representative samples showing the predominant position of the logo is on the lower right corner with respect to the CE Marking Certification label or to the right of the QR code label.

The remaining 394 devices with hologram logos were inspected for the occurrence of the indicators of counterfeiting described in Part V above.

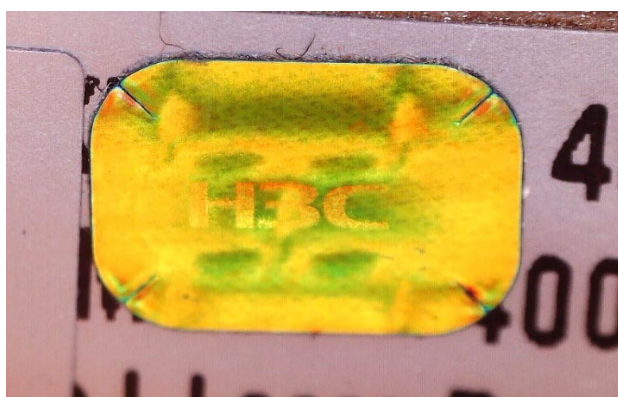
4. The most common indicator of counterfeiting observed in the hologram logos is the off-centered word “H3C” found in a total of **331** hologram logos, or **84.0% of the inspected 394 logos**. These include: 32 labels with the left shift (median 0.58mm); 134 labels with the right shift (median 0.64mm); 20 labels with the up shift (median 0.5mm) and 192 labels with the down shift (median 0.64mm). Certain logos were observed with the word “H3C” shifted in more than one direction (for example, right-shift and down-shift); each such logo was counted as one in the 331 number. The photos illustrating the off-center position of the word “H3C” in the logos are provided as Figure 12 below.



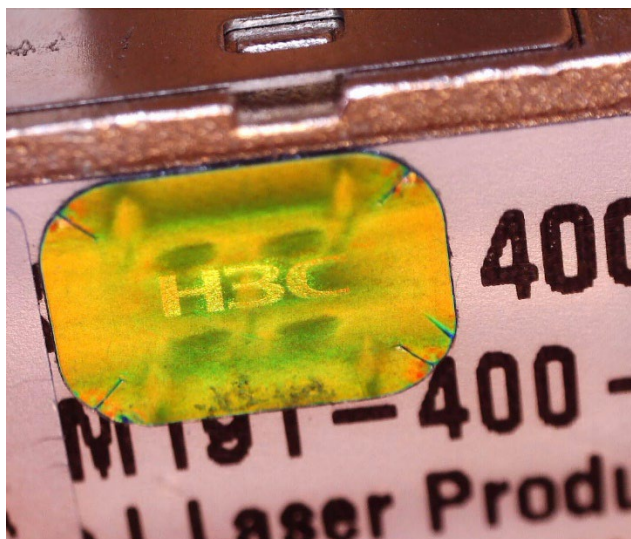
center of “H3C” right-shifts and downshifts



center of "H3C" downshifts



center of "H3C" left-shifts



center of "H3C" up-shifts

Figure 12. Photos of representative samples showing the logo of H3C is not centered in the label.

5. A total of **14** hologram labels inspected (**3.6% of 394 transceivers**) showed signs of delaminated surface protective film (marked as “delamination”). Photos illustrating such delamination of labels is provided in Figure 13 below.

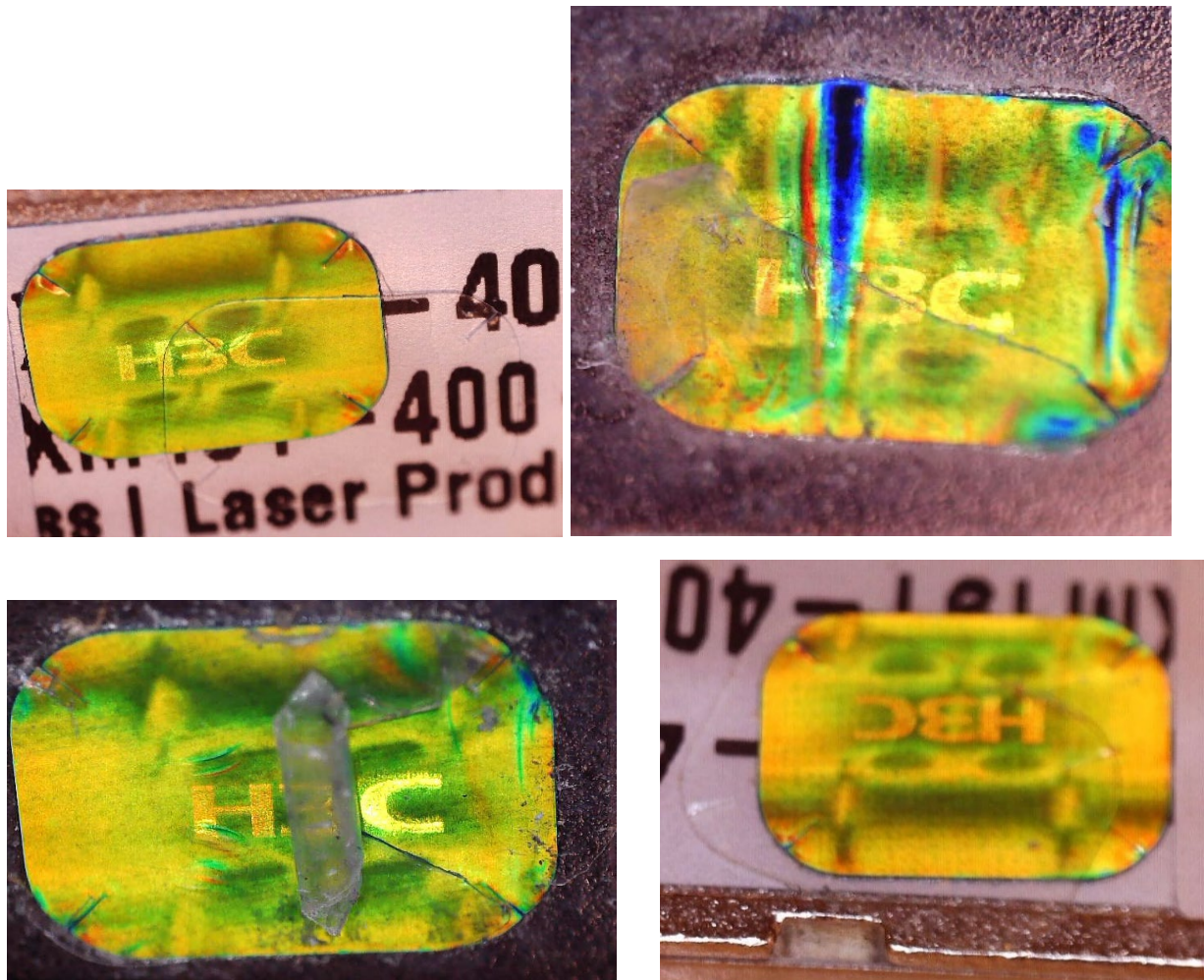


Figure 13. Photos of representative samples of delamination of top protective films.

The verification report also noted holographic logos with “flying off” (completely detached) top layers, as illustrated in Figure 4 above. I observed a number of such detachments as illustrated in Figure 14 below but did not count them separately as an indicator of counterfeiting because my testing methodology did not allow for a reliable quantification of the completely detached top layers.

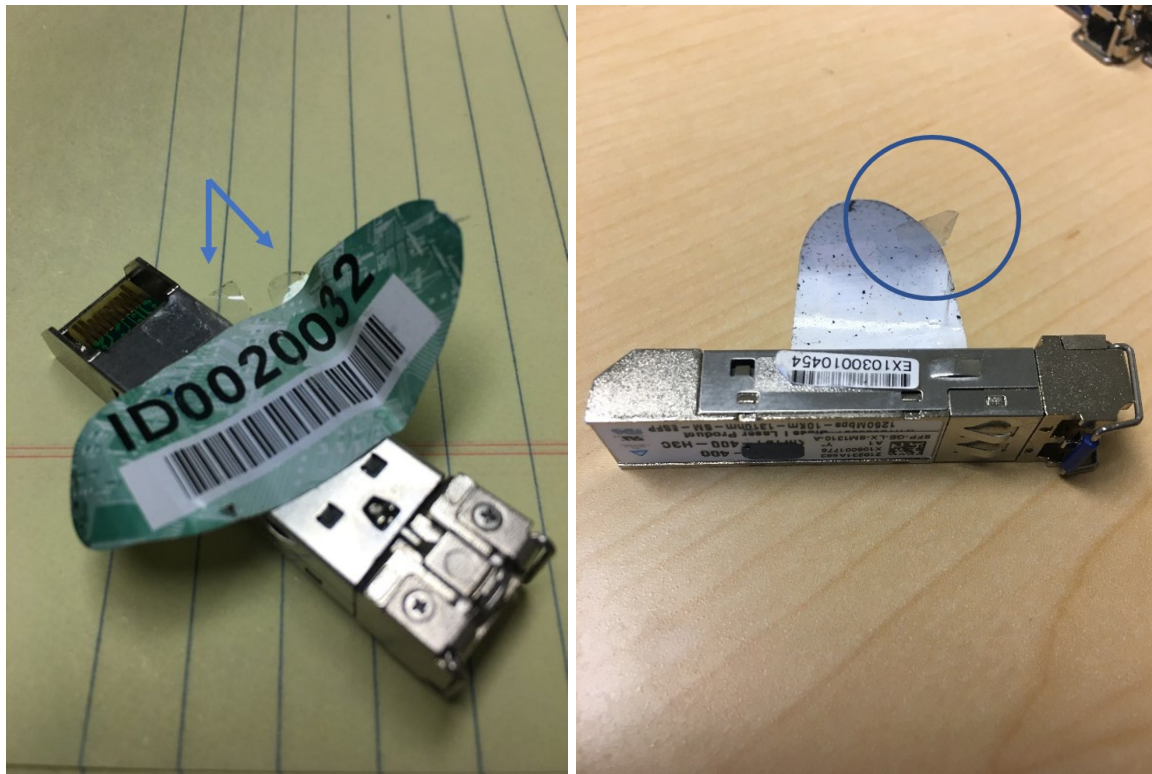


Figure 14. Photos of representative samples of fly-off of top protective films taken by cell phone camera.

6. From the above **394** hologram labels, a total of **47** hologram labels inspected are partially damaged. These labels were measured to record the off-center position of the word “H3C” on the label, but I was not able to take more quantitative assessment with respect to other indicator of counterfeiting specified by H3C’s bulletin.

7. A total of **54** hologram labels inspected (**13.7%**) do not display clear edge of the array vertical dots when the transceiver is tilted at an angle of 27.6° with respect to the left (marked as “Unclear dots from left angle”). Photos illustrating such logos are provided as Figure 15 below. This is clear distinguished from the optical recordings of the labels showing clear edges of bright vertical dots, when the receiver is tilted at an angle of 27.6° with respect to the right. Photos illustrating such logos pictured with right tilt angles are provided as Figure 16 below. I had to place the samples and the wedge

vertically and take these photos using my cell phone camera because the depth of field of the microscope is insufficient to record the complete label at the specific inclination angle of the sample.

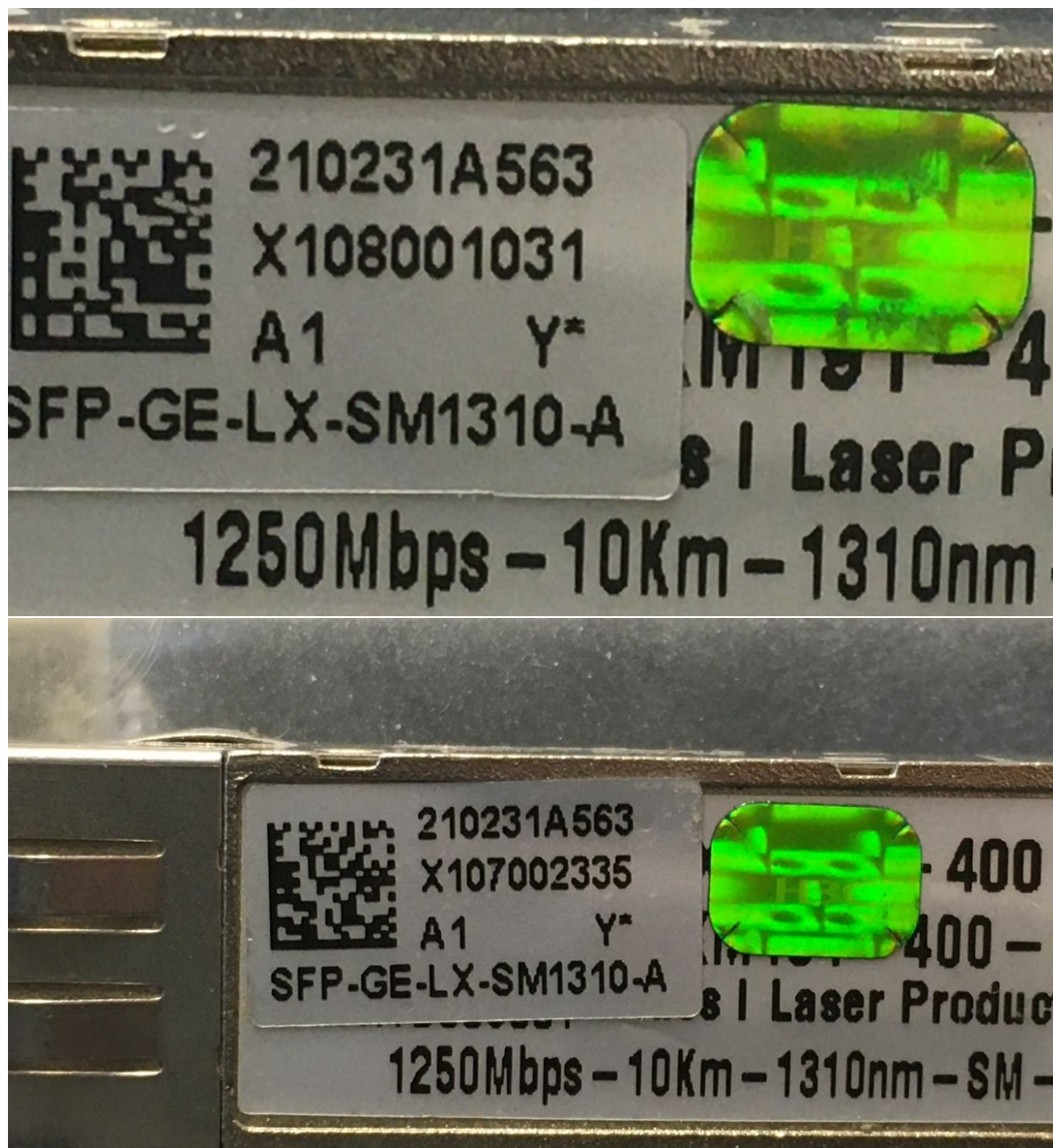


Figure 15. Photos of representative samples with hologram labels of unclear bright vertical dots when the sample is tilted at an angle of 27.6° with respect to the left.



Figure 16. Photos of representative samples with hologram labels showing clear edges of bright vertical dots when the is tilted at an angle of 27.6° with respect to the right.

8. The H3C verification report describes some logos as carrying a “H.3C” hologram label illustrated in Figure 4 above. Under white-light illumination specified in the test methodology, I found logos with a pronounced center-dot reflection that

overlaps with the bottom-left part of the number “3,” creating an appearance of an elongation or a dot at its end. See Figure 17 below for illustration.



Figure 17. Photos of representative samples showing a pronounced reflection of the center dot that overlaps with the number “3”.

I observed the same effect in the two pictures of the logos provided by Plaintiffs (Exhibit 6 to this report). However, I did not find logos with a separately printed dot between “H” and “3C,” and did not include any in the total count of the logos showing indicators of counterfeiting.

I also note from the “H.3C” picture in the H3C verification report (Figure 4 above) that there are scratches or tears visible in the high-magnification image, and a dark vertical line appearing on the photo crossing the number 3 which could have created an appearance of a separated dot.

9. A total of 51 labels inspected (12.9% of 394 labels) showed no observable indicators of counterfeiting featured in the H3C bulletin or the verification report.

It is my opinion that the majority of the hologram labels inspected (343 of 394, or 87.1%) show indicators of counterfeiting described in the H3C security bulletin and the verification report.

I declare under penalty of perjury that the foregoing is true and correct, and if called as a witness I would testify competently thereto.

Dated: December 16, 2019
Boston, Massachusetts


Signed: 
Nicholas Xuanlai Fang

Table 1: Summary of inspected hologram logos

Total transceivers	779	
Transceivers with completely damaged holograms	235	
Transceivers with old (Chinese) holograms	150	
Total holograms inspected	394	Percentage of logos*
Holograms with no observable indications of counterfeiting	51	12.9%
Total holograms with indicators of counterfeiting	343	87.1%
Off-centered word "H3C"	331	84.0%
Left shift	32 (median shift 0.58mm)	
Right shift	134 (median shift 0.64mm)	
Up shift	20 (median shift 0.5mm)	
Down shift	192 (median shift 0.64mm)	
Unclear dots from left angle	54	13.7%
Delaminated surface protective film	14	3.6%

* The percentages do not add up to 100% because of the logos with more than one indicator of counterfeiting.

Within the 343 logos with indicators of counterfeiting:

- 1 logo was identified only with problem of delamination
- 11 logos were identified only with problem of unclear dots viewed from left angle
- 331 logos were identified with off-centered word "H3C"

Within the 331 off-centered logos:

- 13 logos were identified in combination with problem of delamination
- 47 logos were identified with partially damaged labels and no further conclusive measurement besides shift
- 43 logos were identified in combination with problem of unclear dots viewed from left angle

EXHIBIT 1

NICHOLAS FANG

*Professor of MIT/MechE Department,
Office: 3-449D, 77 Massachusetts Ave, Cambridge, MA 02139
<http://web.mit.edu/nanophotonics>*

Education:

Ph.D.	University of California, Los Angeles	2004
M. S.	Nanjing University, China	1998
B. S.	Nanjing University, China	1996

Selected Honors and Awards:

ASME Pi-Tau-Sigma Gold Medal	2006
Award of Excellence in Advising, UIUC	2007
TR35 Young Innovators	2008
SME Young Manufacturing Engineer Award	2009
NSF CAREER Award	2009
Xerox Faculty Award, UIUC	2010
Invited Participant of Frontier of Engineering by National Academy of Engineering	2010
Cambridge Who's Who Professional of the Year in Higher Education Category	2010
ICO Prize/Ernest Abbe Medal by the International Commission of Optics	2011
ASME Chao and Trigger Young Manufacturing Engineer Award	2013
Fellow, International Society for Nanomanufacturing (ISNM)	2013

Teaching Experience:

Optics and Photonics, Materials, Manufacturing, Thermal-Fluidic Sciences, Sensor Technologies

Selected External Professional Service

Editor in Chief, Journal of Micro- and Nano-Manufacturing	2018-Present
Co Editor-in-Chief, Frontiers in Optics and Photonics,	2014-present
Co-organizer, ASME Symposium on Acoustic/Phononic Metamaterials	2009- 2013
Co-organizer, MRS Symposium on Metamaterials	2006, 2011, 2012
Technical Committee, CLEO/QELS	2011, 2012
Technical Committee, ICALEO Nanomanufacturing	2009-now
Expert Witness, Westlaw Round Table Group	2009- present
Board member, Heroyk Company	2015- present
User Committee, Center of Nanoscale Materials, Argonne National Laboratory	2009-2012

Publications of Nicholas X. Fang

Professor Fang, together with his research group and collaborators, has published over 150 peer-reviewed archival journal publications; over 90 conference proceedings papers, 4 book chapters, and he is an inventor on one issued and several pending U.S. Patents. Professor Fang has mentored 11 M.S. and 30 Ph.D. theses as well as several postdoctoral associates.

Selected Journal Publications: (from 150 journal articles, cited over 18000 times as of 2019)

1. Fang, N., H. Lee, C. Sun, and X. Zhang, "Sub-Diffraction-Limited Optical Imaging with a Silver Superlens," *Science*, 308: 5721, 534-537, 2005
2. XH Li, C Liu, SP Feng, NX Fang, "Broadband Light Management with Thermochromic Hydrogel Microparticles for Smart Windows", *Joule* 3:1, 290-302, 2019
3. Z Liu, H Du, J Li, L Lu, ZY Li, NX Fang, "Nano-kirigami with giant optical chirality", *Science advances* 4 (7), eaat4436, 2018
4. Tony Low, Andrey Chaves, Joshua D Caldwell, Anshuman Kumar, Nicholas X Fang, Phaeton Avouris, Tony F Heinz, Francisco Guinea, Luis Martin-Moreno, Frank Koppens, "Polaritons in layered Two Dimensional materials", *Nature Materials*, 16, 182-194 (2017)
5. Y. E Lee, O. D Miller, MT H. Reid, S. G Johnson, N. X Fang, "Computational inverse design of non-intuitive illumination patterns to maximize optical force or torque", *Optics Express*, 25, 6757-6766(2017)
6. Zheng Jie Tan, Dafei Jin, Nicholas X. Fang, "High-precision broadband measurement of refractive index by picosecond real-time interferometry", *Applied Optics* 55, 6625 (2016)
7. Jeffrey B. Chou, Yi Xiang Yeng, Yoonkyung E. Lee, Andrej Lenert, Veronika Rinnerbauer, Ivan Celanovic, Marin Soljacic, Nicholas X. Fang, Evelyn N. Wang and Sang-Gook Kim, "Enabling Ideal Selective Solar Absorption with 2D Metallic Dielectric Photonic Crystals", *Adv. Mater.*, 26, 8041(2014)
8. Cui Y., K. H. Fung, J. Xu, H. Ma, J. Yi, S. He, and N. X. Fang, "Ultra-broadband Light Absorption by a Sawtooth Anisotropic Metamaterial Slab", *Nano Letters*, Vol 12:3, pp 1443-1447, (2012)
9. Wu W., Y. Liu, E. Kim, Z. Yu, N. Fang, C. Sun, X. Zhang, Y. R. Shen, S. Y. Wang and R. S. Williams, "Mid-IR Metamaterials Fabricated by Nanoimprint Lithography," *Applied Physics Letters*, 90:6, Art No. 063107, 2007.
10. Choi S., M. Yan, I. Adesida, K.H. Hsu, and N. X. Fang, "Ultradense Gold Nanostructures Fabricated using Hydrogen Silsesquioxane Resist and Applications for Surface-enhanced Raman Spectroscopy," *Journal of Vacuum Science and Technology*, 27:6, 2640-2643, 2009

Patents and Patent Applications:

1. N. Fang, P. M. Ferreira, K. H. Hsu, P. Schultz, and A. Kumar, "Direct Nanoscale Patterning of Metals Using Polymer Electrolytes," US Patent No. 7,998,330, 2011.
2. X. Li, N. Fang, P. Ferreira, W. Chern, I. Chun, K. Hsu, "Method of Forming an Array Of High Aspect Ratio Semiconductor Nanostructures", US Patent No. 8980656, 2015.
3. C.M Spadaccini, G. Farquar, T. Weisgraber, S. Gemberling, N. Fang, J. Xu, M. Alonso, H. Lee, "High Resolution Projection Micro Stereolithography System And Method", US Patent Application number 2015/0309473, filed 2011.
4. Maxim Shusteff, Christopher M Spadaccini, Nicholas Fang, Robert Matthew Panas, Johannes Henriksson, Brett Kelly, Allison E Browar, "Multi-beam resin curing system and method for whole-volume additive manufacturing", US Patent Application US20180015672A1, filed 2016.
5. N. Fang, C. G. Xia and A. M. Cox, "Three-Dimensional Microfabricated Bioreactors with Embedded Capillary Network", US Patent Application, 20110033887, 2011.
6. N. Fang and J. Xu, "Low-cost, Light-weight, Passive Hearing Protector", US Patent Application, 62/192124, 2015
7. N. Fang and N. Viard, "Subwavelength Acoustic Metamaterial with Tunable Acoustic Absorption", US Patent Application, 62/248377, 2015
8. Wei Q, Su K, Fang N and Zhang X, "Micro-Electro-Mechanical Band-Pass Filters for Radio Frequency Signal Processing", US patent application, PCT/US05/35304.
9. B. Azeredo, N. X Fang, P. M. Ferreira, X. Han, , K. H. Hsu, K. E Jacobs, A. Kumar, "Direct nanoscale patterning of surfaces by electrochemical imprinting", PCT/US2011/025886.
10. C. Zhao, Y. Liu, Y. Zhao, N. Fang, and T. J. Huang, "A Reconfigurable Plasmofluidic Lens", US Patent application, 61/864,373.
11. Zhang, X., N. Fang, and C. Sun, "High-Speed Plasmonic Nano-Optical Microscope," UC provisional patent pending, 2005-174.
12. H. Lee and N. Fang, "Method of Large Area Three Dimensional Microfabrication Using Combined Digital Micromask and Droplet on Demand", MIT provisional patent pending, Case 16334.

Technical Consulting since 2009, for multiple patent cases related to optical imaging, pharma manufacturing, fluid and thermal sciences

EXHIBIT 2

List of Publications of Nicholas X. Fang, from 2010 to 2019

Papers in Referred Journals:

1. Hsu, K., P. M. Ferreira and N. X. Fang, "Controlled Directional Growth of Silver Micro Wires on a Solid Electrolyte Surface," *Applied Physics Letters*, 96:2, art.no.024101, (2010).
2. Chaturvedi, P., W. Wu, V. J. Logeeswaran, Z. Yu, M. S. Islam, S. Y. Wang, R. S. Williams and N. X. Fang, "A Smooth Optical Superlens," *Applied Physics Letters*, 96:4, art.no. 043102, (2010).
3. Chern, W., Hsu K., Chun I.-S., de Azeredo B. P., Ahmed N., Kim K-H, Zuo J., Fang N., Ferreira P., and Li X., "Nonlithographic Patterning and Metal-Assisted Chemical Etching for Manufacturing of Tunable Light-Emitting Silicon Nanowire Arrays", *Nano Letters*, 10:5, pp 1582-1588, (2010).
4. Hsu, K., J. Back, K. H. Fung, P. Ferreira, M. Shim, and N. X. Fang, "SERS EM-field Enhancement Study through Fast Raman Mapping of Sierpinski Carpet Arrays," the *Journal of Raman Spectroscopy*, 41:10, pp 1124-1130, (2010).
5. Chaturvedi P. and N. X. Fang, "Sub-Diffraction Limited Far Field Imaging in Infrared," *Frontiers of Physics in China*, 5:3, pp. 324-329, (2010).
6. Cui Y., J. Xu, S. He and N. X. Fang, "Plasmon Assisted Optical Curtain," *Plasmonics*, (2010), DOI: 10.1007/s11468-010-9152-9.
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EXHIBIT 3

H3C 品牌主机、硬盘和光模块防伪公告 V1.1

为保障消费者权益，维护市场秩序，防止假冒产品扰乱正常的市场竞争机制，杭州华三通信技术有限公司（简称 H3C）宣布，在 H3C 品牌主机、硬盘和光模块产品上使用防伪标签（2010 年 5 月 10 日起从旧版防伪标签切换为新版防伪标签）。

此次设备防伪标签技术的升级，将使消费者更容易辨别 H3C 产品的真伪，更好地保护消费者的合法权益免受侵害。

旧版防伪标签和新版防伪标签对比如下：

	旧主机标签	新主机标签	旧模块标签	新模块标签
图案				

本文主要介绍 H3C 品牌主机、硬盘和光模块的防伪验证方式：

1、主机、硬盘验证方式：

1.1、主机、硬盘所使用的新版防伪标签，从不同角度可以看到不同的点，具体如下图：



右边



左边



上边



下边

注：老版防伪标签已经停用，故不再介绍物理防伪特征。

1.2、主机、硬盘所使用的新版防伪标签和老版防伪标签，均含有明码和暗码（涂层覆盖），可以到下述链接输入 **H3C 序列号(条码)**、**防伪明码**、**防伪暗码**进行防伪验证：

条码防伪查询：<http://channel.h3c.com/channel/system/SearchTrueCode.jsp>

具体查询方式，请参见该页面的辅助说明。

1.3、产品本体带有防伪标签的主机、硬盘，产品一次包装箱外侧会有防伪提示标签。如下图：



注：部分主机、硬盘产品，经 H3C 评估无需纳入防伪标签管理范围，因此产品本体无防伪标签，产品一次包装箱外侧无防伪提示标签。

2、光模块验证方式：

2.1、光模块所使用的新版防伪标签，从不同角度可以看到不同的点，具体如下图：



右边



左边



上边



下边

注：老版防伪标签早已停用，故不再介绍物理防伪特征。

2.2、光模块所使用的新版防伪标签和老版防伪标签，均不含有明码和暗码，可以到下述链接输入 **H3C 序列号(条码)** 进行防伪验证：

条码防伪查询：<http://channel.h3c.com/channel/system/SearchTrueCode.jsp>

具体查询方式，请参见该页面的辅助说明。

2.3、由于光模块防伪标签不含明码和暗码，因此建议用户对于光模块产品增加上电校验。

对于市面上常用的 12 种光模块（具体型号见附件），2008 年 3 月 31 日后出厂的设备会逐步增加对这些光模块生产厂家的判断，对于非原厂认证的光模块，会

主动向日志主机和网管软件发送告警信息，用户也可以通过 Display transceiver interface 命令来查看光模块厂家信息。

举例说明：

```
<H3C> display transceiver interface
GigabitEthernet1/1 transceiver information:
Transceiver Type       : 1000BASE_LX_SFP
Connector Type         : LC
Wavelength(nm)         : 1310
Transfer Distance(km)   : 10(9um)
Digital Diagnostic Monitoring : YES
Vendor Name             : H3C
Ordering Name           : SFP-GE-LX10-SM1310
```

此处应为 YES，表示有诊断功能。显示为 NO 表示非 H3C 模块或者是公

此处应为 H3C，表示模块的生产厂家

a、对于上述 12 种光模块，如果生产日期在 2008 年 3 月 31 日之前，设备可能会出现误告警信息。您在使用中有任何疑问，可以联系 H3C 客服热线进行确认。

b、为了保障消费者的合法权益，降低非原厂认证模块的使用风险，建议您购买原厂光模块。H3C 公司只对原厂产品提供相应的维保服务。

附：在 2008 年 3 月 31 日后采用加密措施的 12 种光模块编号：

编号	产品描述	产品型号
1	光模块-SFP 100M/155M-多模模块-(1310nm, 2km, LC)	SFP-FE-SX-MM1310-A
2	光模块-SFP 100M/155M-单模模块-(1310nm, 15km, LC)	SFP-FE-LX-SM1310-A
3	光模块-SFP 100M/155M-单模模块-(1310nm, 40km, LC)	SFP-FE-LH40-SM1310
4	光模块-SFP 100M/155M 单模长距模块-(1550nm, 80km, LC)	SFP-FE-LH80-SM1550
5	光模块-SFP-GE-多模模块-(850nm, 0.55km, LC)	SFP-GE-SX-MM850-A
6	光模块-SFP-GE-单模模块-(1310nm, 10km, LC)	SFP-GE-LX-SM1310-A
7	光模块-SFP-GE-单模模块-(1310nm, 40km, LC)	SFP-GE-LH40-SM1310
8	光模块-SFP-GE-单模模块-(1550nm, 40km, LC)	SFP-GE-LH40-SM1550
9	光模块-SFP 千兆 BIDI 光模块-TX1310/RX1490, 10km, LC	SFP-GE-LX-SM1310-BIDI
10	光模块-SFP 千兆 BIDI 光模块-TX1490/RX1310, 10km, LC	SFP-GE-LX-SM1490-BIDI
11	光模块-SFP 百兆 BIDI 光模块-TX1310/RX1550, 15km, LC	SFP-FE-LX-SM1310-BIDI
12	光模块-SFP 百兆 BIDI 光模块-TX1550/RX1310, 15km, LC	SFP-FE-LX-SM1550-BIDI



文档名称

文档密级

如有疑问，可咨询 H3C 客服热线：400 810 0504 （拨通后按 6 号键）

本指导书到此结束。

H3C brand host, hard drives and optical modules security bulletin V1.1

SourceURL: http://www.h3c.com.cn/Service/Service_Notice/201005/675683_30005_0.htm

H3C brand host, hard drives and optical modules security bulletin V1.1

To protect the interests of consumers, maintaining market order and prevent counterfeit products disrupt the normal market competition mechanism, Hangzhou H3C Technologies Co., Ltd. (H3C) announced that the use of security labels on H3C brand host, hard drives and optical module products (2010 5 Since switching from the old anti-counterfeit labels for the new month on the 10th security label).

The equipment upgrade security labels and technology, will make it easier for consumers to identify the authenticity of the H3C products, to better protect the legitimate rights and interests of consumers against infringement.

Old and the new security labels security labels contrast as follows:



This paper describes the security authentication H3C brand hosts, hard drives and optical modules:

1 , the host, hard Disk authentication Methods:

1.1, the host, the new security labels used in hard disk, from a different perspective, you can see the different points, specifically the following figure:



The upper right side of the left lower

Note: The old version of the security label has been disabled, it is no longer describes the physical security features.

1.2, the host, the hard disk used the old version of the new anti-counterfeit labels and security labels, contain codes and secret code (coat coverage), can go to the following link to enter the H3C serial number (barcode), security codes, security code security verification dark:

Barcode Security Check: <http://channel.h3c.com/channel/system/SearchTrueCode.jsp>

Specific inquiries, please refer to assist the page's instructions.

1.3, the host body of the product with security labels, hard drives, security products once outside of the box will prompt label As shown below:



Note: Some hosts, hard disk products, the H3C security label to assess the scope of management without inclusion, so Product body no security label, the product once outside of the box without security prompts labels.

2, the Optical module authentication Methods:

2.1, the new anti-counterfeit labels optical modules used, from a different perspective, you can see the different points, specifically the following figure:



The upper right side of the left lower

Note: The old version of the security labels already disabled, it is no longer describes the physical security features.

2.2, optical module uses the old version of the new anti-counterfeit labels and security labels, do not contain codes and password, go to the following link to enter the H3C serial number (barcode) conducted security verification:

Barcode Security Check: <http://channel.h3c.com/channel/system/SearchTrueCode.jsp>

Specific inquiries, please refer to assist the page's instructions.

2.3, due to the optical module security labels contain codes and password, so the user is encouraged to increase the power light modules check.

12 kinds of commonly available in the market for optical modules (specific models see Annex), after March 31, 2008 the factory equipment will gradually increase to these optical module manufacturers to determine, for non-factory-certified optical modules, will take the initiative to the log host and network management software to send alarm information, users can transceiver interface command to view the optical module manufacturers information Display.

For example:

```

<H3C> display transceiver interface
GigabitEthernet1/1 transceiver information:
Transceiver Type      : 1000BASE_LX_SFP
Connector Type       : LC
Wavelength(nm)       : 1310
Transfer Distance(km) : 10(9um)
Digital Diagnostic Monitoring : YES
Vendor Name          : H3C
Ordering Name         : SFP-GE-LX10-SM1310

```

此处应为 YES，表示有诊断功能。显示为 NO 表示非 H3C 模块或者是公

此处应为 H3C，表示模块的生产厂家

a, for the above-mentioned 12 kinds of optical modules, if the production date prior to March 31, 2008, the device may occur false alarm information. You have any questions in use, you can contact the customer service hotline H3C confirmation.

b, in order to protect the legitimate rights and interests of consumers, reduce the risk of non-original authentication module, we recommend that you buy the original optical modules. H3C's only original products provide the appropriate maintenance services.

PS: In the future, March 31, 2008 using encryption measures 12 kinds of optical module ID:

Serial number	Product Description	Product Type
	Optical module -SFP 100M / 155M- multimode module - (1310nm, 2km, LC)	SFP-FE-SX-MM1310-A
	Optical module -SFP 100M / 155M- singlemode module - (1310nm, 15km, LC)	SFP-FE-LX-SM1310-A
	Optical module -SFP 100M / 155M- singlemode module - (1310nm, 40km, LC)	SFP-FE-LH40-SM1310
	Optical module -SFP 100M / 155M long distance single-mode module - (1550nm, 80km, LC)	SFP-FE-LH80-SM1550
	Optical module -SFP-GE- multimode module - (850nm, 0.55km, LC)	SFP-GE-SX-MM850-A
	Single-mode optical module -SFP-GE- module - (1310nm, 10km, LC)	SFP-GE-LX-SM1310-A
	Single-mode optical module -SFP-GE- module - (1310nm, 40km, LC)	SFP-GE-LH40-SM1310
	Single-mode optical module -SFP-GE- module - (1550nm, 40km, LC)	SFP-GE-LH40-SM1550
	BIDI optical module -SFP Gigabit optical modules -TX1310 / RX1490,10km, LC	SFP-GE-LX-SM1310-BIDI
	BIDI optical module -SFP Gigabit optical modules -TX1490 / RX1310,10km, LC	SFP-GE-LX-SM1490-BIDI
	Fast optical module -SFP BIDI optical module -TX1310 / RX1550,15km, LC	SFP-FE-LX-SM1310-BIDI
	Fast optical module -SFP BIDI optical module -TX1550 / RX1310,15km,	SFP-FE-LX-

If in doubt, consult H3C Hotline: 4008100504 (after dialing press the key on the 6th)

This is the end of this guide book.

H3C brand host, hard drives and optical modules security bulletin V1.1

SourceURL: http://www.h3c.com.cn/Service/Service_Note/201005/675683_30005_0.htm



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H3C brand host, hard drives and optical modules security bulletin V1.1

To protect the interests of consumers, maintaining market order and prevent counterfeit products, Hangzhou H3C Technologies Co., Ltd. (H3C) announced that the use of security optical module products (2010 5 Since switching from the old anti-counterfeit labels for the The equipment upgrade security labels and technology, will make it easier for consumers to to better protect the legitimate rights and interests of consumers against infringement.

Old and the new security labels security labels contrast as follows:

	Old master label	New host label	T
Pattern			mod

This paper describes the security authentication H3C brand hosts, hard drives and c 1 , the host, hard disk authentication methods:

1.1, the host, the new security labels used in hard disk, from a different perspective, you can see the following figure:



The upper right side of the left lower

Note: The old version of the security label has been disabled, it is no longer describes the product information. 1.2, the host, the hard disk used the old version of the new anti-counterfeit labels and security labels (coat coverage), can go to the following link to enter the H3C serial number (barcode), security labels:

Barcode Security check: <http://channel.h3c.com/channel/system/SearchTrueCode>
Specific inquiries, please refer to assist the page's instructions.

1.3, the host body of the product with security labels, hard drives, security products once outside the box below:

<p style="text-align: center;">防伪提示</p> <p>为了您的合法权益,请根据以下提示进行防伪检查:</p> <p>1、请您打开包装后,检查产品上是否有防伪标签,并检查防伪标签是否已被刮开、破坏。</p> <p>2、标签提供了明码、暗码(被刮刮墨覆盖)和产品序列号帮助您确认产品为首次使用的真品;请登陆公司网站www.h3c.com.cn,点击进入条码防伪查询页面,根据网站提示输入上述号码,网站将为您提供识别服务;如果您不是首次输入上述号码,系统将会给出警示信息。</p> <p>如果您有任何疑问,请拨打杭州华三通信技术有限公司服务热线:400 810 0504。</p> <p style="text-align: center;"></p> <p>请注意不要破坏产品上的防伪标签,以免影响您的维权权利。</p> <p>本标签的最终解释权归杭州华三通信技术有限公司所有</p>	<p style="text-align: center;">Counterfeit-proof Notice</p> <p>Please follow the below instruction to verify the product.</p> <p>First, upon taking the product out of the package, please check whether the product security hologram label is intact.</p> <p>Next, please visit the website at www.h3c.com Channel Barcode System, entering the verification serial number to verify the authenticity of the product. If the same information has been entered before, a warning message will be displayed.</p> <p>If you have any doubt, please contact your local H3C representative immediately.</p> <p>To ensure the warranty rights of the product is not to remove or damage the security hologram label.</p> <p>H3C reserve all rights to the final interpretation of the label.</p>
--	---

Note: Some hosts, hard disk products, the H3C security label to assess the scope of management security label, the product once outside of the box without security prompts labels.

2 , the optical module authentication methods:

2.1, the new anti-counterfeit labels optical modules used, from a different perspective, you c following figure:



The upper right side of the left lower

Note: The old version of the security labels already disabled, it is no longer describes the ph 2.2, optical module uses the old version of the new anti-counterfeit labels and security labels the following link to enter the H3C serial number (barcode) conducted security verification:

Barcode Security check: <http://channel.h3c.com/channel/system/SearchTrueCode>
Specific inquiries, please refer to assist the page's instructions.

2.3, due to the optical module security labels contain codes and password, so the user is en modules check.

12 kinds of commonly available in the market for optical modules (specific models see Annex equipment will gradually increase to these optical module manufacturers to determine, for no the initiative to the log host and network management software to send alarm information, i view the optical module manufacturers information Display.

For example:

```
<H3C> display transceiver interface
GigabitEthernet1/1 transceiver information:
Transceiver Type          : 1000BASE_LX_SFP
Connector Type            : LC
Wavelength(nm)           : 1310
Transfer Distance(km)     : 10(9um)
Digital Diagnostic Monitoring : YES
Vendor Name               : H3C
Ordering Name             : SFP-GE-LX10-SM1310
```

此处应为
诊断功能。
示非 H3C 模

此处应
示模块

a, for the above-mentioned 12 kinds of optical modules, if the production date prior to Marc information. You have any questions in use, you can contact the customer service hotline H: b, in order to protect the legitimate rights and interests of consumers, reduce the risk of no recommend that you buy the original optical modules. H3C's only original products provide t PS: In the future, March 31, 2008 using encryption measures 12 kinds of optical module ID:

Serial number	Product Description	Product Type
1	Optical module -SFP 100M / 155M- multimode module - (1310nm, 2km, LC)	SFP-FE-SX-MM1310-A
2	Optical module -SFP 100M / 155M- singlemode	

	module - (1310nm, 15km, LC)	SFP-FE-LX-SM1310-A
3	Optical module -SFP 100M / 155M- singlemode module - (1310nm, 40km, LC)	SFP-FE-LH40-SM1310
4	Optical module -SFP 100M / 155M long distance single-mode module - (1550nm, 80km, LC)	SFP-FE-LH80-SM1550
5	Optical module -SFP-GE- multimode module - (850nm, 0.55km, LC)	SFP-GE-SX-MM850-A
6	Single-mode optical module -SFP-GE- module - (1310nm, 10km, LC)	SFP-GE-LX-SM1310-A
7	Single-mode optical module -SFP-GE- module - (1310nm, 40km, LC)	SFP-GE-LH40-SM1310
8	Single-mode optical module -SFP-GE- module - (1550nm, 40km, LC)	SFP-GE-LH40-SM1550
9	BIDI optical module -SFP Gigabit optical modules - TX1310 / RX1490,10km, LC	SFP-GE-LX-SM1310-BIDI
10	BIDI optical module -SFP Gigabit optical modules - TX1490 / RX1310,10km, LC	SFP-GE-LX-SM1490-BIDI
11	Fast optical module -SFP BIDI optical module - TX1310 / RX1550,15km, LC	SFP-FE-LX-SM1310-BIDI
12	Fast optical module -SFP BIDI optical module - TX1550 / RX1310,15km, LC	SFP-FE-LX-SM1550-BIDI

If in doubt, consult H3C Hotline: 4008100504 (after dialing press the key on the 6th)
This is the end of this guide book.

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EXHIBIT 4

对“北京程于团伙售假案件”查扣光模块鉴定材料

一、 鉴定结论

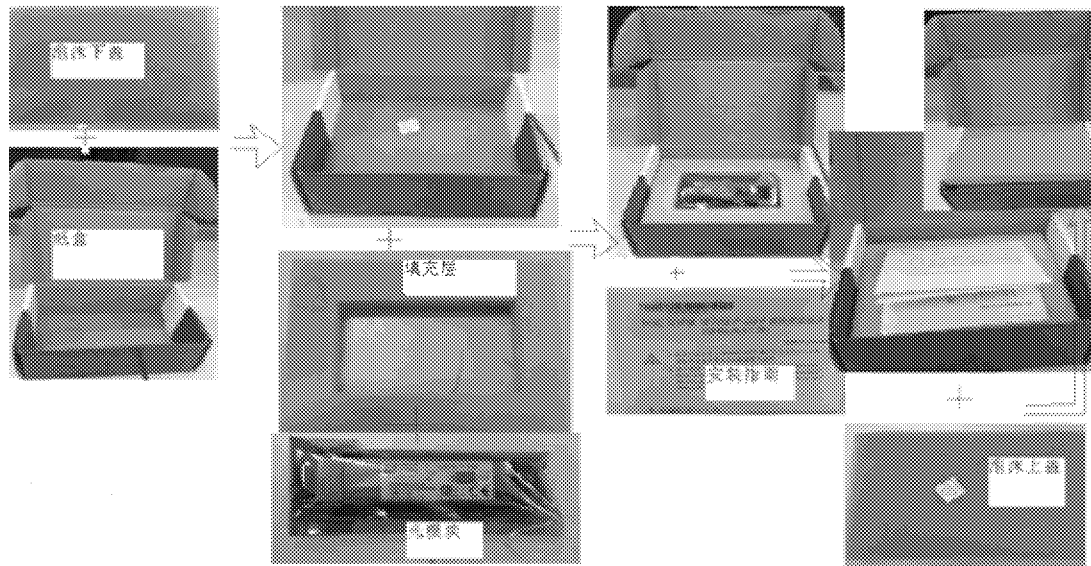
对“北京程于团伙售假案件”查扣光模块从产品包装、产品外观两个方面与H3C 正品进行了逐一比对。经鉴定，所查扣光模块绝大多数与我司正品存在明显差异。鉴定结果为商标侵权。具体如下：

二、 鉴定内容

（一）产品包装比对

1、H3C 产品外包装情况：

H3C 品牌光模块外包装为红白相间带瓦楞纸盒。包装盒内装有红色防震、防静电泡棉。光模块按照防静电工艺要求放在折叠的银色防静电袋中。包装盒及防静电袋各自有封口胶进行封口。具体见图示：



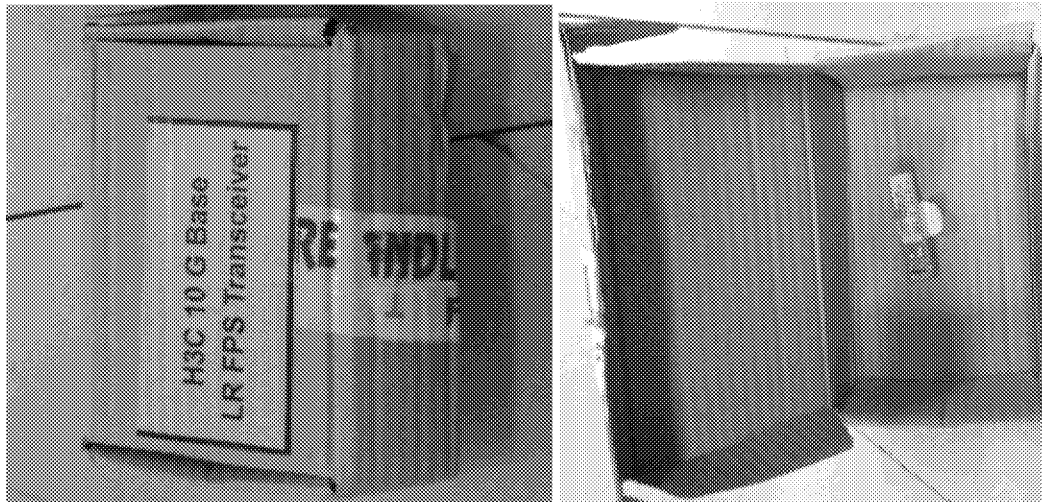
图（1） H3C 正品光模块包装示意图



图（2） H3C 正品光模块防静电袋

2、被鉴定物品外包装情况：

扣押产品没有华三产品工艺标准的外包装盒、防震防静电泡棉填充材料、防静电胶袋。而是将几十个裸露的光模块放在一个气泡袋中，然后再装入一个麻粉纸盒里面。与正品的外包装及运输环境、产品包装完全不同。具体见图示：



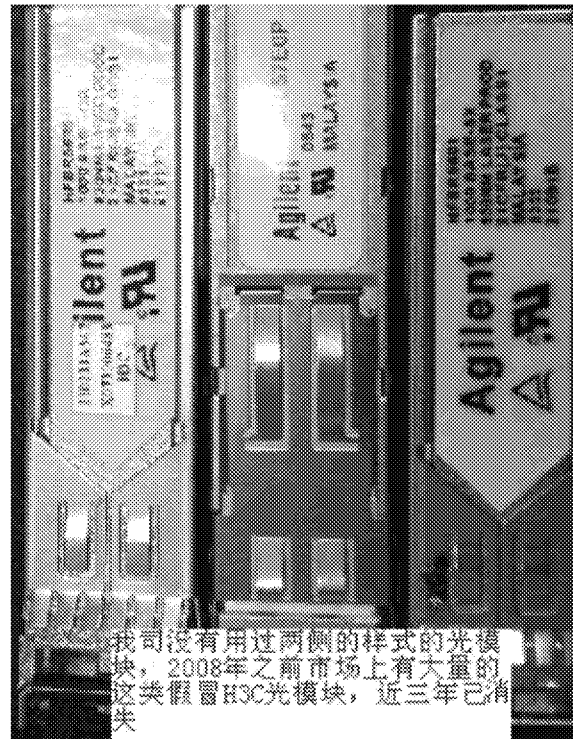
图（3） 扣押产品的外包装



图（4） 扣押产品的包装材料

(二) 产品外观对比

1、大量查扣产品与我司光模块正品本体外表不一致



图（5） 扣押产品与正品模块外观不同（2008 年前这样的假货较多）

2、大量查扣产品本体上粘贴的标签与正品不一致

(1) 大量查扣产品的标签粘贴位置不一致 五花八门

H3C 正品光模块本体上粘贴的条码标签、防伪标签有严格工艺规范要求，由经过培训的工人在流水线上正规化生产，故同型号光模块标签粘贴位置是一致的。同时，H3C 光模块标签是一次性有效的，揭开即破损失效，即黏贴后是不可被完整剥离光模块本体后重新完整黏贴到其他位置。

而扣押产品的标签粘贴位置不一致，且粘贴不规整，粘贴在各种不同位置的情形均有，详见下图：

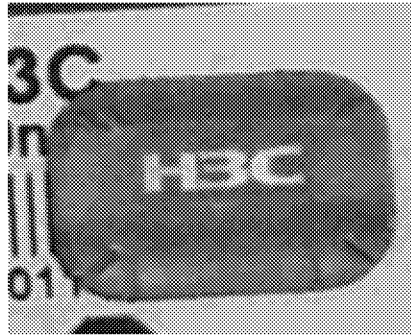


图（6） 扣押产品上标签粘贴位置凌乱

从标签（含防伪标签）粘贴情况可以判断，这些光模块是由不熟悉华三技术工艺、不具备生产技术要求的人员凭想象加工出来的。

(2) 扣押产品防伪标签异常，为假冒标签

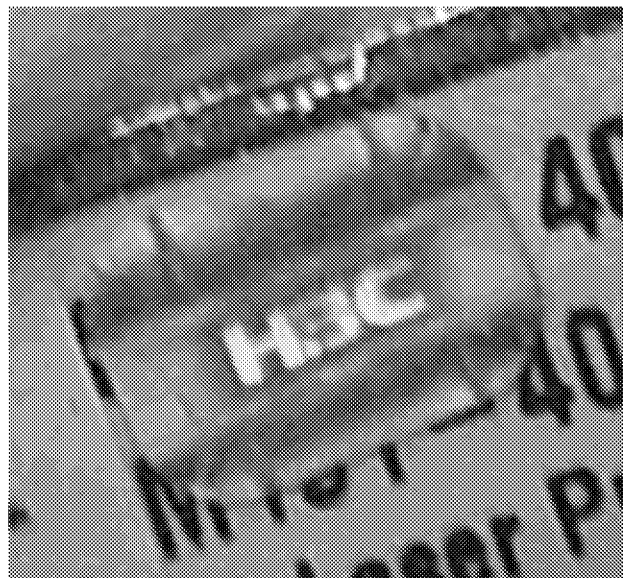
H3C 正品的防伪标签色彩鲜艳，可以从不同角度看出不同个数的圆点，在防伪标签正中有“H3C”字样，具体见下图：



图（7） 正品光模块防伪标签，H3C 居标签正中

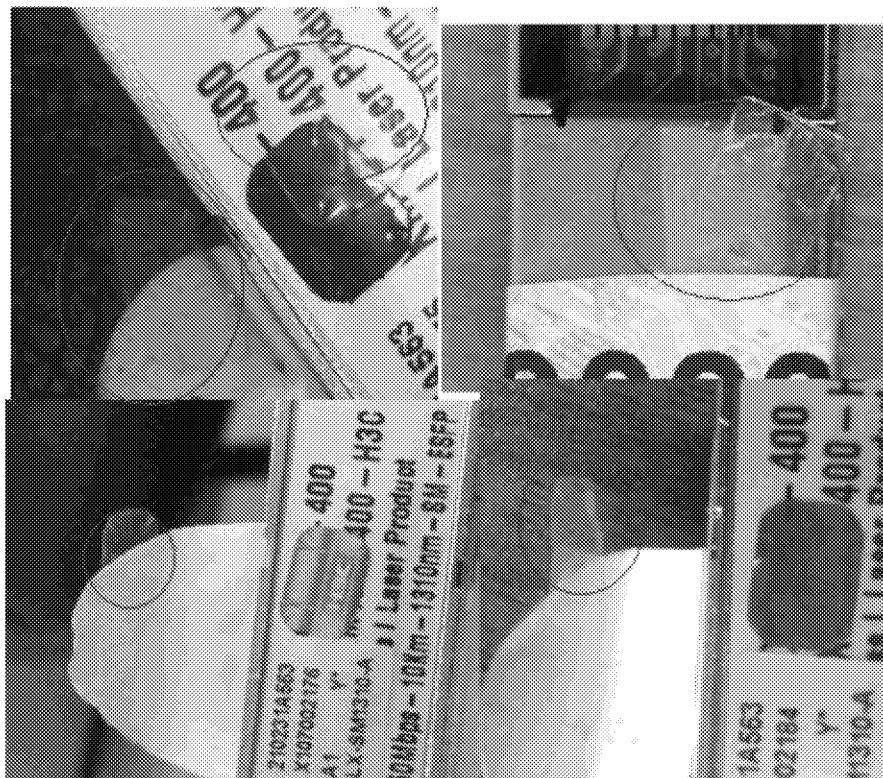
而扣押产品的防伪标签存在诸多问题，具体见下：

A)、部分 H3C 的 LOGO 被印成了“H. 3C”（该类型假冒标签在 2012 年底北京警方查获的龙谷鸿图案中曾大量出现）。



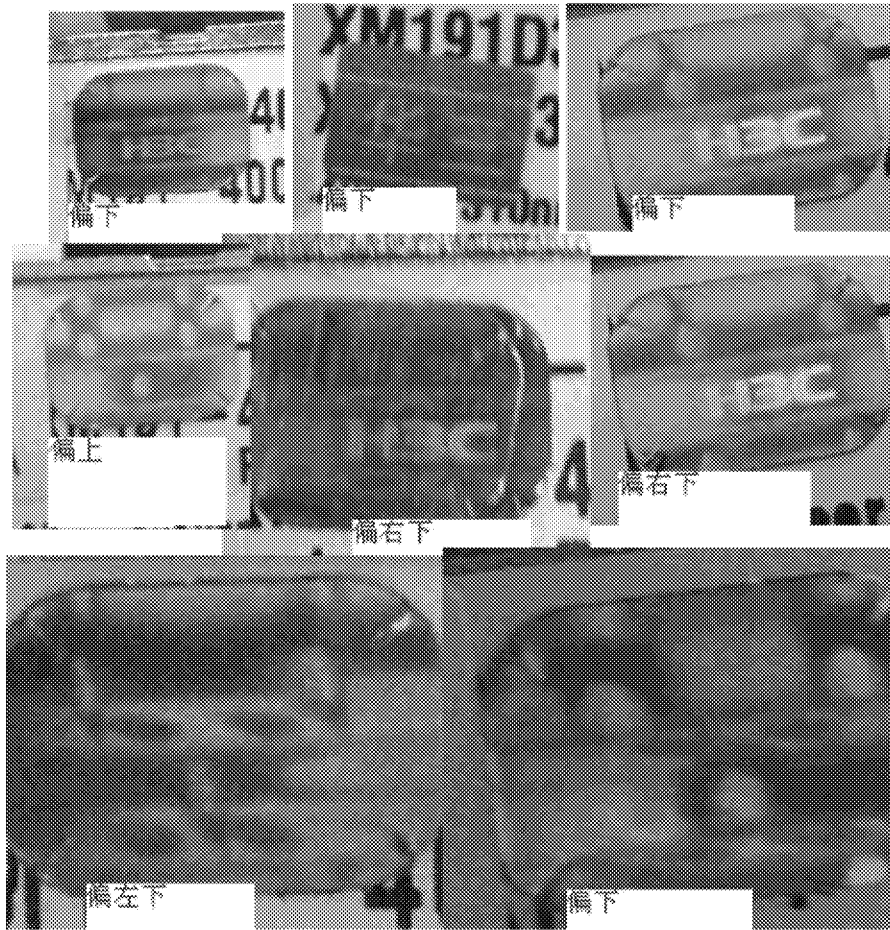
图（8） H.3C 的防伪标签

B)、大量查扣产品的防伪标签表层轻易就“飞走”了，即出现极易分层脱落的现象，且色彩黯淡。具体见图示：



图（9） 防伪标签表层“飞走”

C)、大量查扣产品防伪标签上的 H3C 字样印偏，不在标签的中心位置。具体见图示：



图（10） 防伪标签中 H3C 不居中

在扣押的 700 余件光模块产品中，基本上所有的被扣押产品都存在以上一种或多种异常（与正品的不一致）现象。鉴定受时间所限，没有对以上各种异常数量的多少进行精确统计。但是，这并不影响对这批查扣产品的整体鉴定结论，即以上标签（含防伪标签）异常，足以说明被扣押的这些光模块至少大多数都确定是假冒 H3C 产品。

3、查扣产品没有与正品一致的《安装使用说明书》，查扣产品没有提供产品使用说明书。

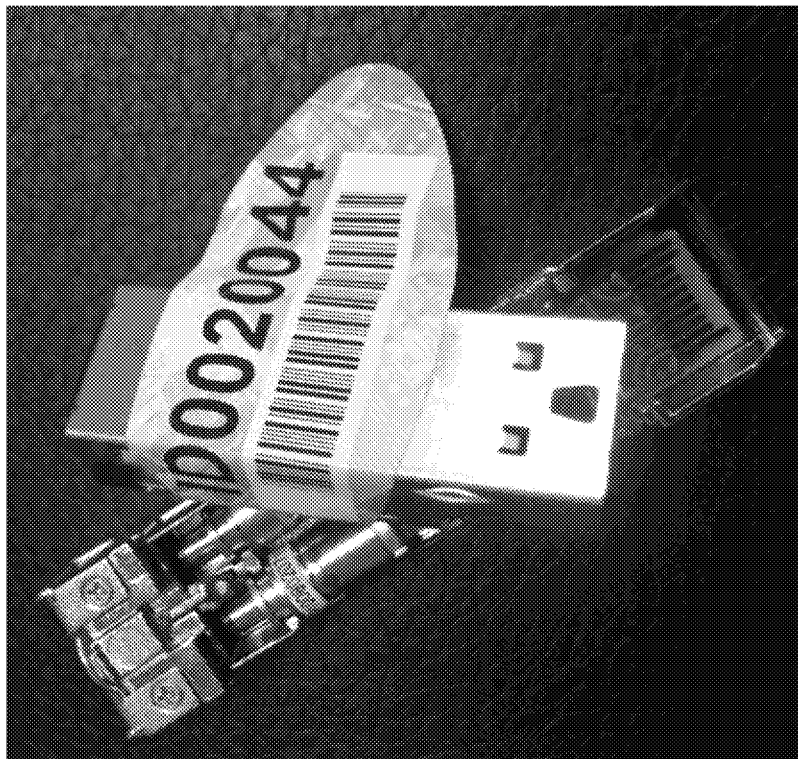
4、查扣产品存在其它影响产品性能的问题

1) 查扣产品中有部分在模块本体上写有“坏”的字样；



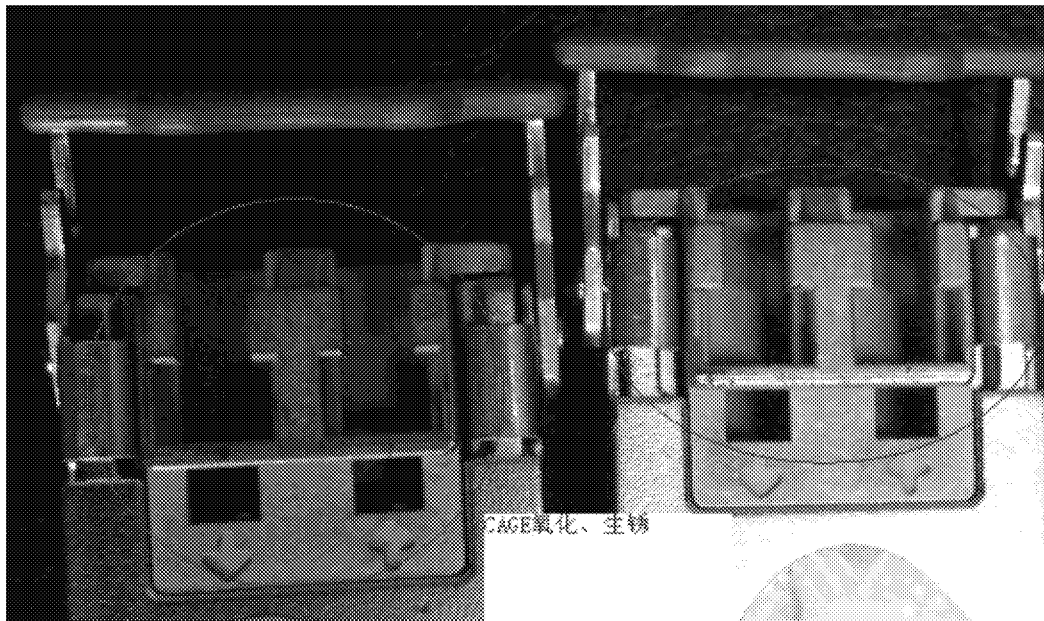
图（11） 模块上写有“坏”的字样

2) 查扣产品中有部分光模块外壳脱落，并有不明厂家标贴标识，具体见图
示：



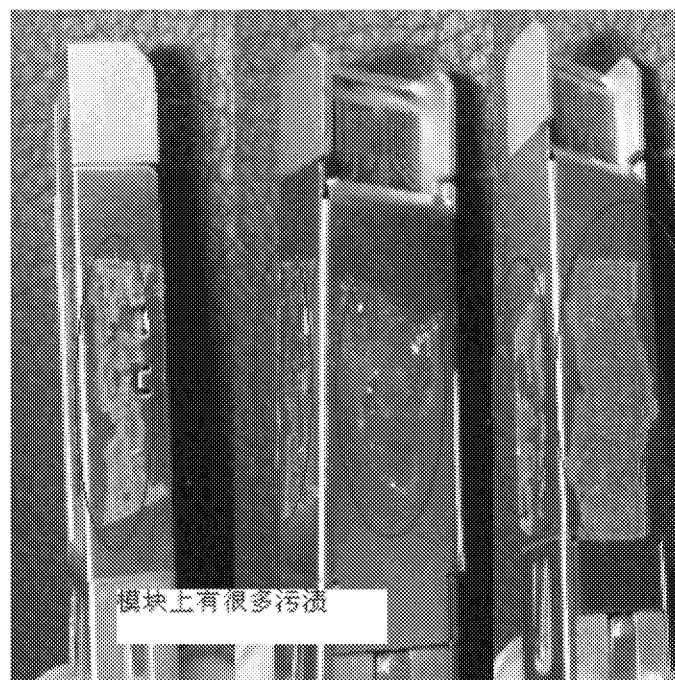
图（12） 光模块外壳脱落，有不明厂家标贴标识

3) 查扣产品中有很多光模块外壳氧化生锈情况



图（13） 光模块外壳氧化、生锈

4)、查扣产品中有很多外壳上有不明污渍。该污渍可能是在设备更改时留下的印迹。



图（14） 光模块上有污渍

三、特别说明：

鉴定时受现场临时搭建交换机网络测试环境等硬件条件限制，因此未对其电性能进行进一步的测试。从大量被鉴定物的物理特征来判定，可以认定该批扣押产品外观各异，存在很多作假痕迹，这种明显假冒的物品上电检测没有实

际意义。因此，我们未对该批扣押产品的电性能作进一步鉴定。

光模块上电检测的目的有两条：第一，检验电性能是否合格；第二，查看内存中写入的产品特征字段。

1、市面上同类光模块还有不少，其中大多数光模块（甚至包括部分假冒H3C品牌的光模块）都可以通过电性能检测。电性能是否能通过检测，与产品是否假冒商标之间没有必然联系。就如同假冒品牌的电视机可能照样可以收看电视节目一样。

2、在理论上、在打假实践中都证明：光模块内存中的产品特征字段是可能被造假者通过类似黑客的手法改写的。并且软件特点决定了这种改写是不会留下痕迹的，不像标签造假那样总会有细微的差别被看出来。

鉴于以上两点，上电检测不能作为判断产品是真品的条件。故上电检测实际上是没有意义的。

四、该批扣押产品存在严重商标侵权并可能导致恶劣社会影响

这批扣押产品存在明显的商标侵权，并且从根本上无法保障其品质功能，流落到社会上必将严重侵害消费者利益、侵犯华三知识产权，更有甚者，可能给国家、社会、经济建设造成不可估量的后果、损失。

1、从社会层面上看：

光模块产品作为网络通信设备之间的“关口”，起着光电信号转换的重要作用，被称为信息高速公路的枢纽。光模块如果性能不合格、或者性能不稳定一旦损坏，对网络设备的直接影响是造成大面积设备通信故障（亦称：关口不通）。被扣押产品中包含有大量万兆级别的光模块，这类光模块一般用于大型网络骨干线路建设，如国家三金工程、城市高铁项目、航空项目、金融系统、高等教育系统等。如果使用了没有品质保障的假冒光模块受损，将引起骨干网络的通信中断。如遇特殊时期（如自然灾害、突发性事件处理等），这种损坏将造成重大损失，带来恶劣的社会影响，破坏社会稳定，其后果将无法估量。

2、从企业经营层面上看：

在网络时代，这种因为使用了假冒光模块而引发的网络瘫痪，造成

客户财务信息丢失、重要科研成果和客户信息丢失，对客户经营造成重大损失，同时也将给 H3C 带来重大经济损失，对 H3C 品牌信誉造成重大损害，这种损害远远高出假冒模块的市场价格。

PLAINTIFFS' OFFICE TRANSLATION OF DEF0002807-DEF0002817

Identification of seized transceivers in the "Beijing Cheng/Yu counterfeit sales case"

The product packaging and product appearance of the seized transceivers in the "Beijing Cheng/Yu counterfeit sales case" were compared with H3C genuine product. After identification, the vast majority of the seized transceivers examined are found to be significantly different from our genuine products. The result of the identification is trademark infringement, details as follows:

Identification content

Product packaging comparison

1. H3C product packaging:

The H3C transceiver is packaged in red and white with corrugated boxes. The box is equipped with red shockproof and antistatic foam. The transceiver is placed in a folded silver anti-static bag in accordance with the anti-static process requirements. The packaging box and the anti-static bag are each sealed with a sealing glue. See the illustration for details:

Figure (1) H3C genuine transceiver packaging schematic

Figure (2) H3C genuine transceiver anti-static bag

2. The outer packaging of the identified items:

The seized products do not have the outer packaging box of the H3C product technology standard, the anti-shock anti-static foam filling material, and the anti-static plastic bag. Instead, dozens of bare transceivers are put in a bubble bag and then loaded into a hemp toned box. It is completely different from the genuine outer packaging and transportation environment and product packaging. See the illustration for details:

Figure (3) The outer packaging of the seized product

Figure (4) Packaging materials for seized products

(2) Comparison of product appearance

1. A large number of seized products are inconsistent with our transceivers.

Figure (5) The seized product is different from the original module (more fakes like this before 2008)

2. A large number of tags attached to the product body are inconsistent with the genuine product.

(1) The label attachment position of a large number of seized products is inconsistent.

The bar code label and anti-counterfeit label attached to the H3C genuine transceiver body have strict technical specifications, and are regularly produced by trained workers on the assembly line. Therefore, the labeling position of the same type transceiver label is consistent. Meanwhile,

the H3C transceiver label is valid at one time and is damaged if removed. That is, after the adhesive is attached, the label cannot be completely removed from the transceiver body and then completely reattached to other locations.

The labeling position of the seized product is inconsistent, and the paste is not regular, and it is pasted in various positions. See the following figure:

Figure (6) The label placement position on the seized product is messy

It can be judged from the labeling of the label (including the anti-counterfeit label) that these transceivers are processed by the imagination of those who are not familiar with the technology of H3C and do not have the technical requirements for production.

(2) The anti-counterfeit label of the seized product is abnormal and is a counterfeit label.

H3C's authentic anti-counterfeit labels are colorful, and you can see different numbers of dots from different angles. There is "H3C" in the center of the anti-counterfeit label. See the following figure for details:

Figure (7) Genuine transceiver security label, H3C home label center

There are many problems with the anti-counterfeiting label of the seized products, as follows:

A) part of the H3C LOGO was printed as "H.3C" (this type of counterfeit label appeared in the Longguhongtu pattern seized by the Beijing police at the end of 2012).

Figure (8) H.3C security label

B) the surface of the anti-counterfeit label of a large number of seized products is easily "flying away," that is, the phenomenon of delamination and detachment is extremely easy, and the color is bleak. See the illustration for details:

Figure (9) Anti-counterfeit label surface "fly away"

C) a large number of H3C type offset on the anti-counterfeit label of the product is not in the center of the label. See the illustration for details:

Figure (10) H3C is not centered in the anti-counterfeit label

Among the more than 700 pieces of transceivers seized, basically all of the seized products have one or more of the above abnormalities (inconsistent with the genuine ones). The identification is limited by time, and there is no accurate statistics on the number of abnormalities above. However, this does not affect the overall appraisal conclusion of the batch of seized products, that is, the above labels (including anti-counterfeiting labels) are abnormal, which is sufficient to indicate that at least most of the seized transceivers are determined to be counterfeit H3C products.

3. The product is not in accordance with the "Installation and Operation Manual," and the product is not provided with the product manual.

4. The checked product has other problems affecting product performance

1) Some of the products in the check-out product have the word “defective” written on the module body;

Figure (11) The word “defective” is written on the module.

2) Some of the transceivers covers are removed from the product, and there are unidentified manufacturers’ logos. See the illustration:

Figure (12) The transceivers cover is detached, and there is an unknown manufacturer’s label.

3) There are many transceivers casings in the product that are oxidized and rusted.

Figure (13) The transceiver casing is oxidized and rusted

4) There are many unidentified stains on the outer casing of the product. This stain may be the footprint left when the device changes.

Figure (14) There are stains on the transceiver

Third, special instructions:

During the identification, the hardware conditions such as the temporary establishment of the switch network test environment were limited, so the electrical performance was not further tested. Judging from the physical characteristics of a large number of identified objects, it can be concluded that the batch of seized products have different appearances and there are many false marks. This kind of obvious counterfeit goods has no practical significance for power-on detection. Therefore, we have not further identified the electrical properties of the seized products.

There are two purposes for power-on detection of a transceiver: first, check whether the electrical performance is qualified. Second, check the product feature field written in the memory.

1. There are still many similar transceivers on the market. Most of the transceivers (including some transceivers with counterfeit H3C brand) can pass the electrical performance test. Whether the electrical performance can pass the test is not necessarily related to whether the product is a counterfeit trademark. Just like a fake brand TV can still play TV shows.

2. In theory, in the practice of counterfeiting, it is proved that the product feature field in the memory of the transceiver may be rewritten by the counterfeiter or a similar hacker. And the characteristics of the software determine that this rewriting will not leave traces, unlike the label fraud, there are always subtle differences.

In view of the above two points, the power-on detection cannot be used as a condition for judging that the product is genuine. Therefore, power-on detection is actually meaningless.

4. The seized products have serious trademark infringement and may cause adverse social impacts.

These seized products have obvious trademark infringement, and fundamentally cannot guarantee their quality functions. Flowing into the society will seriously infringe on the interests of consumers and infringe on the intellectual property rights of H3C. What is more, it may give the country, society and economy immeasurable consequences and losses.

From a social perspective:

As a “gateway” between network communication devices, transceivers play an important role in photoelectric signal conversion and are called the hub of the information highway. If the transceiver fails the performance or the performance is unstable, the direct impact on the network device is caused by a large-area device communication failure (also known as the gateway shutdown). The seized products contain a large number of 10 Gigabit transceivers. These transceivers are generally used for the construction of large-scale network backbone lines, such as the National Sanjin Project, the Urban High-speed Rail Project, the Aviation Project, the Financial System, and the Higher Education System. If the use of a fake transceiver without quality assurance is damaged, communication in the backbone network will be interrupted. In the case of special periods (such as natural disasters, sudden incidents, etc.), such damage will cause significant losses, bring about bad social impacts, and undermine social stability, and the consequences will be incalculable.

From the perspective of business management:

In the network era, this kind of network shackle caused by the use of counterfeit transceivers causes loss of financial information, important scientific research results and loss of customer information, causing significant losses to customers' operations and also causing significant economic losses to H3C. This has caused significant damage to the H3C brand reputation, which is far higher than the market price of counterfeit transceivers.

#	Unit Serial Number	Form Factor	Partial Physically damaged labels: Inconclusive	Delamination	Off centered Hologram	Chinese hologram, no criteria	Wrong positioning of hologram	No hologram label	Unclear dots from left angle	No defect observed
1	100040072320	SFP				chinese hologram, no criteria				
2	100040361088	SFP				chinese hologram, no criteria				
3	100042251666	SFP				chinese hologram, no criteria				
4	100042251668	SFP				chinese hologram, no criteria				
5	100044061421	SFP				chinese hologram, no criteria				
6	100044061426	SFP				chinese hologram, no criteria				
7	100044061429	SFP				chinese hologram, no criteria				
8	100044061782	SFP				chinese hologram, no criteria				
9	100044062810	SFP				chinese hologram, no criteria				
10	100044062830	SFP				chinese hologram, no criteria				
11	100044380538	SFP				chinese hologram, no criteria				
12	100044381410	SFP				chinese hologram, no criteria				
13	100044381545	SFP				chinese hologram, no criteria		No hologram label		
14	610000271948	SFP				chinese hologram, no criteria				

15	013220A00029	XFP	down shift	chinese hologram, no criteria	No defect
16	01T617100059	XFP	down shift		
17	01T617100095	XFP	down shift		
18	01T617100102	XFP	down shift		
19	01T617100103	XFP	left shift		
20	01T617100108	XFP	down shift		
21	03T617100004	XFP	right shift		
22	03T617100007	XFP	right shift		
23	03T617100008	XFP	right shift		
24	03T617100009	XFP	right shift		
25	03T617100010	XFP	down shift		
26	03T617100011	XFP	down shift		
27	03T617100012	XFP	down shift		
28	03T617100016	XFP	down shift		
29	03T617100028	XFP	left shift		
30	03T617100036	XFP	left shift		
31	03T617100037	XFP	down shift		
32	03T617100042	XFP	left shift, down shift		
33	03T617100043	XFP	down shift		
34	04T617100024	XFP			
35	3578394R1A	SFP		chinese hologram, no criteria	No defect
36	98E789N00042	XFP	down shift		
37	9X3220A00122	XFP		chinese hologram, no criteria	
38	9X3220A00229	XFP		chinese hologram, no criteria	
39	9Z3220A00028	XFP		chinese hologram, no criteria	
40	9Z3220A00069	XFP		chinese hologram, no criteria	
41	A0509C00339	SFP		chinese hologram, no criteria	
42	A0510400051	SFP		no hologram label	

43 A0510601360	SFP			no hologram label
44 A0510601425	SFP			no hologram label
45 A0510601978	SFP			no hologram label
46 A0510602093	SFP			no hologram label
47 A0510701172	SFP			no hologram label
48 A0510702108	SFP			no hologram label
49 BP0939440216	SFP	chinese hologram, no criteria		
50 BP0940070079	SFP	chinese hologram, no criteria		
51 BP0942A00317	SFP	chinese hologram, no criteria		
52 BP0942A00318	SFP	chinese hologram, no criteria		
53 BP0944260129	SFP	chinese hologram, no criteria		
54 BP0944260286	SFP	chinese hologram, no criteria		
55 BP0944260330	SFP		no hologram label	
56 BP0944260340	SFP	chinese hologram, no criteria		
57 BP0944260410	SFP	chinese hologram, no criteria		
58 BP0944260593	SFP			no hologram label
59 BP0944260680	SFP			no hologram label
60 BP0944261273	SFP			no hologram label
61 BP0944261291	SFP			no hologram label
62 BP0944370281	SFP	chinese hologram, no criteria		
63 BP0944370285	SFP			No defect
64 BP0944370289	SFP	chinese hologram, no criteria		

65 BP0944370290	SFP	chinese hologram, no criteria	no hologram label
66 BP0944370508	SFP	chinese hologram, no criteria	
67 BP0950100211	SFP		
68 BP1002040275	SFP	chinese hologram, no criteria	
69 BP1009240745	SFP	chinese hologram, no criteria	
70 BP1009250002	SFP		no hologram label
71 BP1009250003	SFP	chinese hologram, no criteria	
72 BP1009250004	SFP		no hologram label
73 BP1009250009	SFP		no hologram label
74 BP1009250012	SFP		no hologram label
75 BP1009250013	SFP		no hologram label
76 BP1009250015	SFP		no hologram label
77 BP1009250019	SFP		no hologram label
78 BP1009250020	SFP		no hologram label
79 BP1009250025	SFP		no hologram label
80 BP1009250043	SFP		no hologram label
81 BP1009250046	SFP		no hologram label
82 BP1009250047	SFP		no hologram label
83 BP1009250048	SFP		no hologram label
84 BP1009250049	SFP		no hologram label
85 BP1009250050	SFP	Wrong positioning of hologram	no hologram label
86 BP1009250062	SFP		no hologram label
87 BP1009250064	SFP		no hologram label
88 BP1009250066	SFP		no hologram label
89 BP1009250068	SFP		no hologram label
90 BP1009250082	SFP		no hologram label
91 BP1009250088	SFP		no hologram label
92 BP1009250090	SFP		no hologram label
93 BP1009250091	SFP		no hologram label
94 BP1009250095	SFP		no hologram label
95 BP1009250096	SFP		no hologram label

96 BP1009250151	SFP			no hologram label
97 BP1009250157	SFP			no hologram label
98 BP1009250159	SFP			no hologram label
99 BP1009250160	SFP			no hologram label
100 BP1009250161	SFP			no hologram label
101 BP1009250162	SFP	chinese hologram, no criteria		no hologram label
102 BP1009250173	SFP			no hologram label
103 BP1009250178	SFP			no hologram label
104 BP1009250180	SFP			no hologram label
105 BP1009250181	SFP	chinese hologram, no criteria		
106 BP1009250182	SFP	chinese hologram, no criteria		no hologram label
107 BP1009250184	SFP			
108 BP1009250185	SFP	chinese hologram, no criteria		
109 BP1009250187	SFP	chinese hologram, no criteria	Wrong positioning of hologram	
110 BP1009250188	SFP	chinese hologram, no criteria		
111 BP1009250189	SFP	chinese hologram, no criteria		no hologram label
112 BP1009250190	SFP			
113 BP1009250191	SFP	chinese hologram, no criteria		
114 BP1009250253	SFP			
115 BP1009250255	SFP	chinese hologram, no criteria		No defect
116 BP1009250258	SFP	chinese hologram, no criteria		
117 BP1009250262	SFP			no hologram label
118 BP1009250267	SFP			no hologram label

119 BP1009250268	SFP			no hologram label
120 BP1009250269	SFP			
121 BP1009250270	SFP	chinese hologram, no criteria	Wrong positioning of hologram	no hologram label
122 BP1009250273	SFP			
123 BP1009250275	SFP	chinese hologram, no criteria		no hologram label
124 BP1009250278	SFP			
125 BP1009250280	SFP	chinese hologram, no criteria		no hologram label
126 BP1009250281	SFP			
127 BP1009250285	SFP	chinese hologram, no criteria		no hologram label
128 BP1009250298	SFP			
129 BP1009250299	SFP	chinese hologram, no criteria		no hologram label
130 BP1009250300	SFP	chinese hologram, no criteria		
131 BP1009250304	SFP	chinese hologram, no criteria		
132 BP1009250305	SFP			
133 BP1009250306	SFP	chinese hologram, no criteria		no hologram label
134 BP1009250307	SFP			no hologram label
135 BP1009250308	SFP	chinese hologram, no criteria		
136 BP1009250309	SFP			
137 BP1009250310	SFP			
138 BP1009250312	SFP			
139 BP1009250322	SFP			
140 BP1009250363	SFP	chinese hologram, no criteria	Wrong positioning of hologram	no hologram label
141 BP1009250367	SFP			no hologram label

142 BP1009250368	SFP		no hologram label
143 BP1009250369	SFP	chinese hologram, no criteria	
144 BP1009250370	SFP		no hologram label
145 BP1009250376	SFP		no hologram label
146 BP1009250382	SFP		no hologram label
147 BP1009250396	SFP		no hologram label
148 BP1009250452	SFP		no hologram label
149 BP1009250470	SFP	chinese hologram, no criteria	
150 BP1009250472	SFP		no hologram label
151 BP1009250473	SFP	chinese hologram, no criteria	
152 BP1009800156	SFP	chinese hologram, no criteria	
153 BP1009800157	SFP	chinese hologram, no criteria	
154 BP1010840002	SFP		no hologram label
155 BP1010840003	SFP		no hologram label
156 BP1010840004	SFP	chinese hologram, no criteria	
157 BP1010840010	SFP	Wrong positioning of hologram	
158 BP1010840022	SFP	chinese hologram, no criteria	no hologram label
159 BP1010840023	SFP		no hologram label
160 BP1010840025	SFP		Unclear dots
161 BP1010840027	SFP	chinese hologram, no criteria	
162 BP1010840028	SFP		no hologram label
163 BP1010840118	SFP	chinese hologram, no criteria	
164 BP1010840121	SFP		no hologram label
165 BP1010840129	SFP		no hologram label

166 BP1010840142	SFP	Wrong positioning of hologram	chinese hologram, no criteria	no hologram label no hologram label
167 BP1010840150	SFP			
168 BP1010840164	SFP			
169 BP1010840165	SFP		chinese hologram, no criteria	
170 BP1010840167	SFP		chinese hologram, no criteria	
171 BP1010840169	SFP		chinese hologram, no criteria	
172 BP1010840173	SFP		chinese hologram, no criteria	no hologram label no hologram label
173 BP1010840177	SFP			
174 BP1010840179	SFP			
175 BP1010840182	SFP		chinese hologram, no criteria	no hologram label no hologram label no hologram label no hologram label
176 BP1010840183	SFP			
177 BP1010840188	SFP			
178 BP1010840193	SFP			
179 BP1010840205	SFP	Wrong positioning of hologram		
180 BP1010840210	SFP			
181 BP1010840213	SFP			
182 BP1010840214	SFP			
183 BP1010840217	SFP		chinese hologram, no criteria	no hologram label no hologram label no hologram label no hologram label
184 BP1010840218	SFP			
185 BP1010840233	SFP		chinese hologram, no criteria	
186 BP1010840247	SFP			
187 BP1010840251	SFP	Wrong positioning of hologram		no hologram label no hologram label
188 BP1010840253	SFP		chinese hologram, no criteria	

189 BP1010840257	SFP	chinese hologram, no criteria	Wrong positioning of hologram	no hologram label no hologram label
190 BP1010840261	SFP			
191 BP1010840267	SFP			
192 BP1010840289	SFP	chinese hologram, no criteria		no hologram label no hologram label
193 BP1010840293	SFP			
194 BP1010840294	SFP			
195 BP1010840379	SFP	chinese hologram, no criteria		no hologram label
196 BP1010840380	SFP			
197 BP1010840382	SFP		Wrong positioning of hologram	no hologram label
198 BP1010840385	SFP		Wrong positioning of hologram	no hologram label no hologram label
199 BP1014550101	SFP			
200 BP1014550103	SFP	chinese hologram, no criteria		no hologram label
201 BP1014550106	SFP			
202 BP1014550107	SFP		Wrong positioning of hologram	no hologram label no hologram label no hologram label no hologram label no hologram label no hologram label
203 BP1014550111	SFP			
204 BP1014550112	SFP			
205 BP1014550114	SFP			
206 BP1014550115	SFP			
207 BP1014550118	SFP			
208 BP1014550171	SFP	chinese hologram, no criteria		no hologram label
209 BP1014550174	SFP			
210 BP1014550177	SFP	chinese hologram, no criteria	Wrong positioning of hologram	no hologram label
211 BP1014550178	SFP			

212 BP1014550180	SFP		no hologram label	
213 BP1014550183	SFP	chinese hologram, no criteria		
214 BP1014550186	SFP		no hologram label	
215 BP1014550187	SFP		no hologram label	
216 BP1014550191	SFP	chinese hologram, no criteria	no hologram label	No defect
217 BP1014550225	SFP			
218 BP1014550228	SFP		no hologram label	
219 BP1014550245	SFP		no hologram label	
220 BP1014550247	SFP	chinese hologram, no criteria		
221 BP1014550250	SFP		no hologram label	
222 BP1014550251	SFP	chinese hologram, no criteria		
223 BP1014550252	SFP		no hologram label	
224 BP1014550259	SFP		no hologram label	
225 BP1014550271	SFP		no hologram label	
226 BP1014550273	SFP	chinese hologram, no criteria		
227 BP1014550274	SFP		no hologram label	
228 BP1014550277	SFP		no hologram label	
229 BP1014550278	SFP	chinese hologram, no criteria		
230 BP1014550279	SFP			Unclear dots
231 BP1014550280	SFP		no hologram label	
232 BP1014550305	SFP		no hologram label	
233 BP1014550306	SFP		no hologram label	
234 BP1014550309	SFP	chinese hologram, no criteria		
235 BP1014550315	SFP			Wrong positioning of hologram
236 BP1014550319	SFP		no hologram label	
237 BP1014550320	SFP		no hologram label	
238 BP1014550324	SFP			
239 BP1014550326	SFP		no hologram label	Unclear dots

240 BP1014550329	SFP	chinese hologram, no criteria	Wrong positioning of hologram	
241 BP1014550330	SFP	chinese hologram, no criteria		
242 BP1014550334	SFP	chinese hologram, no criteria	Wrong positioning of hologram	
243 BP1014550365	SFP	chinese hologram, no criteria		no hologram label
244 BP1014550367	SFP			no hologram label
245 BP1014550369	SFP	chinese hologram, no criteria		
246 BP1014550372	SFP	right shift, down shift		
247 BP1014550375	SFP	chinese hologram, no criteria		
248 BP1014550377	SFP			Physically damaged label
249 BP1014550381	SFP			right shift
250 BP1014550384	SFP			
251 BP1014550386	SFP			no hologram label
252 BP1014550387	SFP			no hologram label
253 BP1014550593	SFP			no hologram label
254 BP1014550594	SFP			no hologram label
255 BP1014550595	SFP			no hologram label
256 BP1014550599	SFP			no hologram label
257 BP1014550600	SFP			no hologram label
258 BP1014550602	SFP			no hologram label
259 BP1014550617	SFP	chinese hologram, no criteria		
260 BP1014550621	SFP			no hologram label
261 BP1014550622	SFP	chinese hologram, no criteria		
262 BP1014550623	SFP			no hologram label
263 BP1014550624	SFP	chinese hologram, no criteria		

264 BP1014550638	SFP	chinese hologram, no criteria	no hologram label
265 BP1014550639	SFP		no hologram label
266 BP1014550640	SFP		no hologram label
267 BP1014550644	SFP		no hologram label
268 BP1014550651	SFP		no hologram label
269 BP1014550652	SFP		no hologram label
270 BP1014550654	SFP		no hologram label
271 BP1014550655	SFP	chinese hologram, no criteria	no hologram label
272 BP1014550660	SFP		no hologram label
273 BP1014550662	SFP		no hologram label
274 BP1014550710	SFP		no hologram label
275 BP1014550743	SFP		no hologram label
276 BP1014550744	SFP		no hologram label
277 BP1014550745	SFP	chinese hologram, no criteria	no hologram label
278 BP1014550749	SFP		
279 BP1014550757	SFP	chinese hologram, no criteria	Wrong positioning of hologram
280 BP1014550759	SFP		no hologram label
281 BP1014550761	SFP	chinese hologram, no criteria	
282 BP1014550765	SFP	chinese hologram, no criteria	
283 BP1014550766	SFP		no hologram label
284 BP1014550767	SFP	chinese hologram, no criteria	
285 BP1014550769	SFP	chinese hologram, no criteria	
286 BP1014550793	SFP		no hologram label
287 BP1014550794	SFP		no hologram label
288 BP1014550797	SFP	chinese hologram, no criteria	

289 BP1014550798	SFP		no hologram label
290 BP1014550800	SFP		no hologram label
291 BP1014550807	SFP		no hologram label
292 BP1014550809	SFP		no hologram label
293 BP1014550830	SFP	chinese hologram, no criteria	no hologram label
294 BP1014550834	SFP		
295 BP1014550851	SFP	chinese hologram, no criteria	no hologram label
296 BP1014550877	SFP		no hologram label
297 BP1014550878	SFP		no hologram label
298 BP1014550879	SFP		no hologram label
299 BP1014550882	SFP	chinese hologram, no criteria	
300 BP1014550884	SFP	chinese hologram, no criteria	no hologram label
301 BP1014550887	SFP		no hologram label
302 BP1014550891	SFP		no hologram label
303 BP1014550894	SFP		no hologram label
304 BP1014550897	SFP		no hologram label
305 BP1014550898	SFP		no hologram label
306 BP1014550899	SFP	chinese hologram, no criteria	no hologram label
307 BP1014550903	SFP		no hologram label
308 BP1014550904	SFP		no hologram label
309 BP1014550905	SFP		no hologram label
310 BP1014550907	SFP		no hologram label
311 BP1014550908	SFP		no hologram label
312 BP1014550910	SFP		no hologram label
313 BP1014550913	SFP		no hologram label
314 BP1014550914	SFP		no hologram label
315 BP1014550916	SFP		no hologram label
316 BP1014550921	SFP		no hologram label
317 BP1014550928	SFP		no hologram label
318 BP1014550964	SFP		no hologram label
319 BP1014550969	SFP	chinese hologram, no criteria	

320 BP1014550971	SFP			no hologram label
321 BP1014551012	SFP		Wrong positioning of hologram	
322 BP1014551013	SFP	right shift	chinese hologram, no criteria	
323 BP1014551026	SFP		chinese hologram, no criteria	
324 BP1014551038	SFP		chinese hologram, no criteria	
325 BP1014551039	SFP			no hologram label
326 BP1014551042	SFP			no hologram label
327 BP1014551043	SFP		Wrong positioning of hologram	
328 BP1014551044	SFP		Wrong positioning of hologram	
329 BP1014551046	SFP		chinese hologram, no criteria	
330 BP1014551102	SFP			no hologram label
331 BP1014551123	SFP			no hologram label
332 BP1014551130	SFP		chinese hologram, no criteria	
333 BP1014551132	SFP		Wrong positioning of hologram	
334 BP1014551136	SFP		chinese hologram, no criteria	
335 BP1014551139	SFP			no hologram label
336 BP1014551142	SFP		chinese hologram, no criteria	
337 BP1014551146	SFP		chinese hologram, no criteria	
338 BP1014551148	SFP			no hologram label
339 BP1014551149	SFP			no hologram label
340 BP1014551150	SFP			no hologram label
341 BP1014551151	SFP			no hologram label
342 BP1014551186	SFP	left shift		

343 BP1014551216	SFP	chinese hologram, no criteria	
344 BP1014551220	SFP	chinese hologram, no criteria	
345 BP1014551221	SFP	chinese hologram, no criteria	no hologram label
346 BP1014551222	SFP		
347 BP1014551224	SFP	chinese hologram, no criteria	
348 BP1014551225	SFP	chinese hologram, no criteria	
349 BP1014551226	SFP	chinese hologram, no criteria	no hologram label
350 BP1014551227	SFP		
351 BP1014551232	SFP	chinese hologram, no criteria	Wrong positioning of hologram
352 BP1014551234	SFP		no hologram label
353 BP1014551235	SFP		no hologram label
354 BP1014551236	SFP		no hologram label
355 BP1014551238	SFP	chinese hologram, no criteria	
356 BP1014551239	SFP		no hologram label
357 BP1014551240	SFP		no hologram label
358 BP1014551241	SFP		no hologram label
359 BP1014551242	SFP	chinese hologram, no criteria	
360 BP1014551244	SFP		Wrong positioning of hologram
361 BP1014551245	SFP		no hologram label
362 BP1014551246	SFP	chinese hologram, no criteria	no hologram label
363 BP1014551264	SFP		no hologram label

364 BP1014551265	SFP		no hologram label
365 BP1014551266	SFP		
366 BP1014551271	SFP	Wrong positioning of hologram	no hologram label no hologram label
367 BP1014551272	SFP	chinese hologram, no criteria	no hologram label
368 BP1014551273	SFP		
369 BP1014551275	SFP	chinese hologram, no criteria	no hologram label
370 BP1014551278	SFP		no hologram label
371 BP1014551279	SFP		no hologram label
372 BP1014551281	SFP		no hologram label
373 BP1014551284	SFP		no hologram label
374 BP1014551285	SFP		no hologram label
375 BP1014551286	SFP	chinese hologram, no criteria	no hologram label
376 BP1014551287	SFP		
377 BP1014551288	SFP	chinese hologram, no criteria	no hologram label
378 BP1014551291	SFP		no hologram label
379 BP1014551292	SFP		no hologram label
380 BP1014551293	SFP	chinese hologram, no criteria	no hologram label
381 BP1014551307	SFP		no hologram label
382 BP1014551347	SFP		no hologram label
383 BP1014551359	SFP	chinese hologram, no criteria	no hologram label
384 BP1014551365	SFP		no hologram label
385 BP1014551376	SFP		no hologram label
386 BP1014551377	SFP		no hologram label
387 BP1014551382	SFP		no hologram label
388 BP1014551390	SFP		no hologram label
389 BP1014551393	SFP		no hologram label
390 BP1014551395	SFP		no hologram label

391 BP1014551397	SFP	chinese hologram, no criteria	Wrong positioning of hologram				
392 BP1015900003	SFP	chinese hologram, no criteria					
393 BP1015900005	SFP	chinese hologram, no criteria					
394 BP1015900006	SFP			no hologram label			
395 BP1021820041	SFP						
396 BP1021820056	SFP						Unclear dots
397 BP1021820058	SFP						
398 BP1021820069	SFP						
399 BP1021820100	SFP						
400 BP1021820103	SFP						
401 BP1021820116	SFP						
402 BP1021820118	SFP						
403 BP1021820122	SFP						
404 BP1021820135	SFP						
405 BP1021820142	SFP						
406 BP1021820143	SFP						
407 BP1021820150	SFP						
408 BP1021820151	SFP						
409 BP1021820158	SFP						
410 BP1021820162	SFP						
411 BP1021820182	SFP						
412 BP1021820200	SFP						
413 BP1021820202	SFP						
414 BP1021820213	SFP						
415 BP1021820217	SFP						
416 BP1021820218	SFP						
417 BP1021820240	SFP						
418 BP1021820247	SFP						
419 BP1021820249	SFP						
420 BP1021820255	SFP						
421 BP1021820256	SFP						
422 BP1021820259	SFP						
423 BP1021820276	SFP						

424 BP1021820286	SFP		down shift	
425 BP1021820288	SFP		right shift	
426 BP1021820308	SFP		down shift	
427 BP1021820312	SFP	Physically damaged label	down shift	
428 BP1021820319	SFP	Physically damaged label	right shift, down shift	
429 BP1021820340	SFP		left shift	
430 BP1021820342	SFP	Physically damaged label	right shift	No defect
431 BP1021820343	SFP			
432 BP1021820352	SFP	Physically damaged label	down shift	
433 BP1021820375	SFP		right shift	Unclear dots
434 BP1021820395	SFP		left shift	Unclear dots
435 BP1021820400	SFP		down shift	
436 BP1021820404	SFP		down shift	
437 BP1021820418	SFP		down shift	
438 BP1021820427	SFP		down shift	
439 BP1021820435	SFP		down shift	
440 BP1021820438	SFP		down shift	
441 BP1021820439	SFP		down shift	
442 BP1021820461	SFP		down shift	
443 BP1021820467	SFP		right shift, down shift	
444 BP1030510001	SFP		down shift	No defect
445 BP1030510004	SFP			
446 BP1030510035	SFP		right shift	Unclear dots
447 BP1030510043	SFP			Unclear dots
448 BP1030510058	SFP		down shift	No defect
449 BP1030510099	SFP			No defect
450 BP1030510123	SFP			No defect
451 BP1030510128	SFP			
452 BP1030510133	SFP			No defect
453 BP1030510138	SFP	Physically damaged label	right shift	
454 BP1030510141	SFP		right shift	
455 BP1030510148	SFP		right shift	
456 BP1030510184	SFP		down shift	
457 BP1030510185	SFP		up shift	
458 BP1030510209	SFP		up shift	Unclear dots
459 BP1030510230	SFP		right shift	Unclear dots
460 BP1030510235	SFP			No defect

SFP	461 BP1030510238	Physically damaged label	Delamination	right shift	Unclear dots
SFP	462 BP1030510254			down shift	
SFP	463 BP1030510256			right shift	
SFP	464 BP1030510258			right shift	
SFP	465 BP1030510263			right shift, down shift	No defect
SFP	466 BP1030510305		Delamination	down shift	
SFP	467 BP1030510316				
SFP	468 BP1030510372			down shift	
SFP	469 BP1030510379			right shift	No defect
SFP	470 BP1030510386			right shift	
SFP	471 BP1030510407	Physically damaged label		right shift	
SFP	472 BP1030510415	Physically damaged label		right shift	
SFP	473 BP1030510416			right shift	Unclear dots
SFP	474 BP1030510437			right shift	
SFP	475 BP1030510446	Physically damaged label		down shift	
SFP	476 BP1030510458			down shift	
SFP	477 BP1030510467			right shift, down shift	Unclear dots
SFP	478 BP1030510473			left shift	
SFP	479 BP1030510476			right shift	
SFP	480 BP1030510478	Physically damaged label		right shift	
SFP	481 BP1030510503			up shift	No defect
SFP	482 BP1030510504			down shift	
SFP	483 BP1030510505			up shift	
SFP	484 BP1030510507				
SFP	485 BP1030510510				No defect
SFP	486 BP1030510519				
SFP	487 BP1030510521		Delamination	right shift	
SFP	488 BP1030510528	Physically damaged label		up shift	
SFP	489 BP1030510538			right shift	No defect
SFP	490 BP1030510543			right shift	
SFP	491 BP1030510568				
SFP	492 BP1030510582				
SFP	493 BP1030510607			down shift	Unclear dots
SFP	494 BP1030510615		Delamination	right shift, down shift	
SFP	495 BP1030510617			shift	
SFP	496 BP1030510620				

496 BP1030510620	SFP	Physically damaged label	down shift	Unclear dots
497 BP1030510622	SFP		right shift	
498 BP1030510635	SFP		left shift	
499 BP1030510641	SFP		down shift	Unclear dots
500 BP1030510671	SFP		right shift	
501 BP1030510701	SFP		down shift	
502 BP1030510704	SFP		right shift	
503 BP1030510705	SFP		right shift	
504 BP1030510722	SFP		right shift	
505 BP1030510737	SFP		right shift	
506 BP1030510742	SFP		right shift	
507 BP1030510744	SFP		right shift	
508 BP1030510806	SFP		right shift	
509 BP1030510808	SFP		right shift, down shift	
510 BP1030510819	SFP	Physically damaged label	down shift	Unclear dots
511 BP1030510844	SFP		right shift	
512 BP1030510849	SFP	Physically damaged label	down shift	
513 BP1030510858	SFP		right shift	
514 BP1030510872	SFP		right shift	
515 BP1030510877	SFP		down shift	Unclear dots
516 BP1030510885	SFP		down shift	
517 BP1030510901	SFP		down shift	
518 BP1030510903	SFP		right shift	
519 BP1030510904	SFP		right shift	
520 BP1030511006	SFP		right shift	
521 BP1030511009	SFP		right shift	
522 BP1030511026	SFP	Delamination	down shift	Unclear dots
523 BP1030511029	SFP		down shift	Unclear dots
524 BP1030511031	SFP		right shift	no hologram label
525 BP1030511058	SFP		right shift	No defect
526 BP1030511066	SFP		right shift	
527 BP1030511068	SFP		right shift	
528 BP1030511072	SFP	Physically damaged label	down shift	Unclear dots
529 BP1030511084	SFP		down shift	
530 BP1030511085	SFP		down shift	
531 BP1030511089	SFP	Physically damaged label	right shift	No defect
532 BP1030511158	SFP			
533 BP1030511163	SFP			

534 BP1030511172	SFP	Physically damaged label	right shift	Unclear dots
535 BP1030511175	SFP	Physically damaged label	down shift right shift	
536 BP1030511190	SFP			
537 BP1030511198	SFP			
538 DW08033267	SFP		chinese hologram, no criteria	
539 EX1017030044	SFP		right shift	
540 EX1017030065	SFP		right shift	
541 EX1017030094	SFP		down shift	
542 EX1017030165	SFP		down shift	
543 EX1017030166	SFP		left shift	No defect
544 EX1017030179	SFP			
545 EX1017030204	SFP		down shift	
546 EX1017030210	SFP		down shift	
547 EX1017030495	SFP		down shift	
548 EX1017030505	SFP		down shift	
549 EX1017030509	SFP		down shift	
550 EX1017030530	SFP		down shift	
551 EX1017030532	SFP		right shift, down shift	Unclear dots
552 EX1017030601	SFP		down shift	
553 EX1017030605	SFP		down shift	
554 EX1017030610	SFP		down shift	
555 EX1017030629	SFP			No defect
556 EX1017030650	SFP		left shift, down shift	Unclear dots
557 EX1017030655	SFP	Physically damaged label	down shift	
558 EX1017030677	SFP		down shift	
559 EX1017030755	SFP			No defect
560 EX1017030768	SFP		down shift	
561 EX1017030771	SFP		down shift	
562 EX1017030776	SFP		down shift	
563 EX1017030800	SFP		down shift	
564 EX1017030881	SFP		right shift	
565 EX1017030884	SFP		down shift	No defect
566 EX1017030886	SFP	Physically damaged label	up shift	
567 EX1017030893	SFP		right shift	

568 EX1017030953	SFP	Physically damaged label	left shift, down shift	
569 EX1017030963	SFP		down shift	
570 EX1020020035	SFP	Physically damaged label	left shift, up shift	
571 EX1020020036	SFP		left shift	No defect
572 EX1020020037	SFP		left shift	
573 EX1020020041	SFP			
574 EX1020020058	SFP		up shift	
575 EX1020020059	SFP		right shift	Unclear dots
576 EX1020020061	SFP		down shift	Unclear dots
577 EX1020020075	SFP		left shift	
578 EX1020020082	SFP	Physically damaged label	down shift	
579 EX1020020127	SFP		down shift	
580 EX1020020129	SFP		right shift	
581 EX1020020503	SFP		down shift	
582 EX1020020517	SFP		right shift	
583 EX1020020554	SFP		up shift	
584 EX1020020559	SFP		left shift	Unclear dots
585 EX1020020581	SFP			
586 EX1020020977	SFP		left shift	Unclear dots
587 EX1020020986	SFP		down shift	
588 EX1020021129	SFP			
589 EX1020021130	SFP		left shift	No defect
590 EX1020021161	SFP		down shift, left shift	
591 EX1020021287	SFP		up shift	
592 EX1020021291	SFP			
593 EX1020021391	SFP		left shift	No defect
594 EX1020021475	SFP		up shift	
595 EX1020021636	SFP		down shift	Unclear dots
596 EX1020021649	SFP			
597 EX1020021679	SFP			No defect
598 EX1020021776	SFP		down shift	No defect
599 EX1020021778	SFP	Physically damaged label	down shift	
600 EX1020021801	SFP		left shift	
601 EX1020021855	SFP		left shift	
602 EX1020022001	SFP		down shift	Unclear dots
603 EX1020022006	SFP		up shift	
604 EX1020050002	SFP		left shift	
605 EX1020050018	SFP		down shift	Unclear dots

606 EX1020050021	SFP			down shift	Unclear dots
607 EX1020050036	SFP			down shift	Unclear dots
608 EX1020050048	SFP	Physically damaged		down shift	
609 EX1020050049	SFP	label		down shift	
610 EX1020050050	SFP			down shift	
611 EX1020050072	SFP	Physically damaged		down shift	
612 EX1020050078	SFP	label		down shift	
613 EX1020050106	SFP			down shift	
614 EX1020050119	SFP			down shift	Unclear dots
615 EX1020050125	SFP			down shift	Unclear dots
616 EX1020050133	SFP		Delamination	down shift	
617 EX1020050138	SFP			right shift, down shift	
618 EX1020050142	SFP			right shift, down shift	
619 EX1020050144	SFP			down shift	
620 EX1020050155	SFP			right shift	
621 EX1020050158	SFP			right shift	
622 EX1021060024	SFP				Unclear dots
623 EX1021060025	SFP	Physically damaged		down shift	
624 EX1021060028	SFP	label		down shift	
625 EX1021060038	SFP			down shift	No defect
626 EX1021060041	SFP			down shift	
627 EX1021060053	SFP			down shift	
628 EX1021060125	SFP			up shift	
629 EX1021060126	SFP		Delamination	right shift, down shift	
630 EX1021060142	SFP	Physically damaged		shift	
631 EX1021060147	SFP	label		down shift	
632 EX1021060149	SFP			down shift	
633 EX1021060401	SFP			right shift, down shift	
634 EX1021060407	SFP			down shift	
635 EX1021060417	SFP			right shift, down shift	
636 EX1021060430	SFP		Delamination	shift	
637 EX1021060436	SFP	Physically damaged		right shift	
638 EX1021060437	SFP	label		right shift	
639 EX1021060577	SFP			down shift	

640	EX1021060580	SFP	Delamination	right shift, down shift		
641	EX1021060581	SFP		down shift		No defect
642	EX1021060584	SFP				
643	EX1021060596	SFP		down shift		
644	EX1030010006	SFP		right shift		
645	EX1030010007	SFP		up shift		No defect
646	EX1030010009	SFP		right shift		
647	EX1030010030	SFP	Physically damaged label		Unclear dots	
648	EX1030010036	SFP		right shift		
649	EX1030010042	SFP		right shift		
650	EX1030010201	SFP				No defect
651	EX1030010207	SFP		left shift		
652	EX1030010208	SFP		down shift		
653	EX1030010209	SFP		right shift		
654	EX1030010238	SFP	Physically damaged label	right shift	Unclear dots	
655	EX1030010288	SFP		down shift		No defect
656	EX1030010380	SFP				
657	EX1030010389	SFP		right shift		No defect
658	EX1030010406	SFP				
659	EX1030010445	SFP		down shift		
660	EX1030010454	SFP	Physically damaged label	right shift	Unclear dots	
661	EX1030010502	SFP		right shift		
662	EX1030010654	SFP		right shift, up shift		
663	EX1030010660	SFP			Unclear dots	
664	EX1030010665	SFP		right shift		No defect
665	EX1030010666	SFP		right shift		
666	EX1030010694	SFP	Physically damaged label	right shift		
667	EX1030010714	SFP		right shift		No defect
668	EX1030010809	SFP		left shift	Unclear dots	
669	EX1030010826	SFP				
670	EX1030010843	SFP				No defect
671	EX1030010849	SFP				No defect
672	EX1030010850	SFP		up shift	Unclear dots	
673	EX1030010851	SFP	Physically damaged label	up shift		

674 EX1030010870	SFP	Physically damaged label	right shift	No defect
675 EX1030010987	SFP		right shift, down shift	
676 EX1030010989	SFP			Unclear dots
677 EX1030010994	SFP		right shift	No defect
678 EX1030010995	SFP		right shift	
679 EX1030011002	SFP		right shift, down shift	
680 EX1030011094	SFP			
681 EX1030011095	SFP			No defect
682 EX1030011146	SFP	Physically damaged label	down shift	
683 EX1030011218	SFP			Unclear dots
684 EX1030011223	SFP		right shift, up shift	
685 EX1030011242	SFP			
686 EX1030011274	SFP	Physically damaged label	right shift	
687 EX1030011285	SFP		right shift	
688 EX1030011363	SFP		right shift, down shift	No defect
689 EX1030011394	SFP		down shift	
690 EX1030011401	SFP			No defect
691 EX1030011403	SFP		right shift	
692 EX1030011414	SFP			
693 EX1030011420	SFP		right shift	
694 EX1030011436	SFP		down shift	left shift
695 EX1030011453	SFP		down shift	
696 EX1030011483	SFP		right shift	
697 EX1030011560	SFP	Physically damaged label	down shift	
698 EX1030011624	SFP		down shift	
699 EX1030011644	SFP		right shift	Unclear dots
700 EX1030011650	SFP			No defect
701 EX1030011713	SFP	Physically damaged label	right shift	
702 EX1030011809	SFP		up shift	Unclear dots
703 EX1030011818	SFP			Unclear dots
704 EX1030011829	SFP			no hologram label
705 EX1030011831	SFP		right shift	No defect

706 G0047468	SFP		chinese hologram, no criteria		No hologram label
707 H11F323	SFP				No hologram label
708 H11F613	SFP				
709 UGH04P4	XFP		down shift		
710 UGH04UY	XFP		chinese hologram, no criteria		
711 UGH04VK	XFP		right shift, down shift		
712 UGJ05DU	XFP		down shift		
713 UGJ05E0	XFP		right shift, down shift		
714 UGJ05EB	XFP	Physically damaged label	right shift		
715 UGJ05FB	XFP		right shift		
716 UGJ05MA	XFP				
717 UGK06H9	XFP		right shift, down shift		No defect
718 UGK07GX	XFP		right shift, down shift		
719 UGK07L7	XFP		right shift		
720 UGK07LT	XFP		right shift		
721 UGK07MJ	XFP	Delamination	down shift		
722 UGK08B7	XFP		down shift		
723 UGK08BD	XFP	Physically damaged label	down shift		
724 UGL01L6	XFP		right shift		
725 UGL01LA	XFP		down shift		
726 UGL050M	XFP		right shift, down shift		
727 UGL050U	XFP		right shift		
728 UGL051E	XFP		down shift		
729 UGL05MF	XFP		down shift		
730 UGL05P1	XFP	Delamination	down shift		
731 UGL05PE	XFP		right shift, down shift		
732 UGL05PJ	XFP		right shift, down shift		
733 UGL05RN	XFP		right shift, down shift		
734 UGL05RZ	XFP		right shift		

735 UGL0550	XFP			right shift, down shift		No defect
736 UGL07DU	XFP					
737 UGL07F2	XFP					
738 UGL07FS	XFP			down shift		
739 UGL07S7	XFP			right shift, down shift		
740 UGL07TS	XFP			right shift		
741 UGL080J	XFP			right shift, down shift		
742 UGL080S	XFP			down shift		
743 UGQ0A2B	XFP				chinese hologram, no criteria	
744 UH207T4	XFP				chinese hologram, no criteria	
745 UH208ZP	XFP				chinese hologram, no criteria	
746 UH30818	XFP				chinese hologram, no criteria	
747 UH8004U	XFP	Physically damaged label		right shift		
748 UH8004Y	XFP	Physically damaged label		down shift		
749 UH8006Z	XFP			down shift		
750 UH8007E	XFP		Delamination	right shift		
751 UHA03LM	XFP				chinese hologram, no criteria	
752 UHA03LQ	XFP			down shift		
753 UHA06PJ	XFP			down shift, left shift		
754 UHA06PP	XFP				no hologram label	
755 UHA07CM	XFP					
756 UHA07D0	XFP	Physically damaged label		right shift		No defect
757 UHA07D3	XFP			down shift		
758 UHA07DF	XFP			down shift		
759 UHA07EZ	XFP			down shift		
760 UHA07FG	XFP			left shift		

Part number	Part description	Physical condition	Physical damage	Label	Physical damage	Label
761 UHA07FR	761 UHA07FR	XF	down shift	no hologram		
762 UHA07GS	762 UHA07GS	XF	down shift			
763 UHA07H8	763 UHA07H8	XF				
764 UHA07MX	764 UHA07MX	XF	down shift			
765 UHA07MZ	765 UHA07MZ	XF	right shift			
766 UHB04KE	766 UHB04KE	XF	down shift			
767 UHB04KG	767 UHB04KG	XF	down shift, left shift			
768 UHB04LE	768 UHB04LE	XF				
769 UHB04LN	769 UHB04LN	XF	down shift			
770 UHB04LT	770 UHB04LT	XF	left shift, down shift			
771 UHJ01ET	771 UHJ01ET	XF				
772 UHQ0ANX	772 UHQ0ANX	XF	down shift			
773 X069000417	773 X069000417	SFP	chinese hologram, no criteria			
774 X083006465	774 X083006465	SFP	chinese hologram, no criteria			
775 X105000169	775 X105000169	SFP	chinese hologram, no criteria			
776 X105000189	776 X105000189	SFP	chinese hologram, no criteria			
777 X108001154	777 X108001154	SFP	right shift			
778 X108001232	778 X108001232	SFP	right shift			
779 X108001320	779 X108001320	SFP	up shift			

EXHIBIT 6

